NEC

MOS INTEGRATED CIRCUIT

μPD42S4260, 424260

4 M-BIT DYNAMIC RAM
256 K-WORD BY 16-BIT, FAST PAGE MODE, BYTE READ/WRITE MODE

Description

The μPD42S4260, 424260 are 262,144 words by 16 bits dynamic CMOS RAMs. The fast page mode and byte read/write mode capability realize high speed access and low power consumption.

Besides, the μPD42S4260 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh.

These are packaged in 44-pin plastic TSOP (II) and 40-pin plastic SOJ.

Features

- 262,144 words by 16 bits organization
- Single +5.0 V ±10 % power supply
- Fast access and cycle time

Part number	Power consumption Active (MAX.)	Access time (MAX.)	R/W cycle time (MIN.)	Fast page mode cycle time (MIN.)
★ μPD42S4260-60, 424260-60	880.0 mW	60 ns	110 ns	40 ns
μPD42S4260-70, 424260-70	880.0 mW	70 ns	130 ns	45 ns
μPD42S4260-80, 424260-80	797.5 mW	80 ns	150 ns	50 ns

- The μPD42S4260 can execute $\overline{CAS}$ before $\overline{RAS}$ self refresh

Part number	Refresh cycle	Refresh	Power consumption at standby (MAX.)
μPD42S4260	512 cycles / 128 ms	$\overline{CAS}$ before $\overline{RAS}$ self refresh, $\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	0.825 mW (CMOS level input)
μPD424260	512 cycles / 8 ms	$\overline{CAS}$ before $\overline{RAS}$ refresh, $\overline{RAS}$ only refresh, Hidden refresh	5.5 mW (CMOS level input)

- Multiplexed address inputs ... Row address: A0 to A8, Column address: A0 to A8

The information in this document is subject to change without notice.

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The mark ★ shows major revised points.

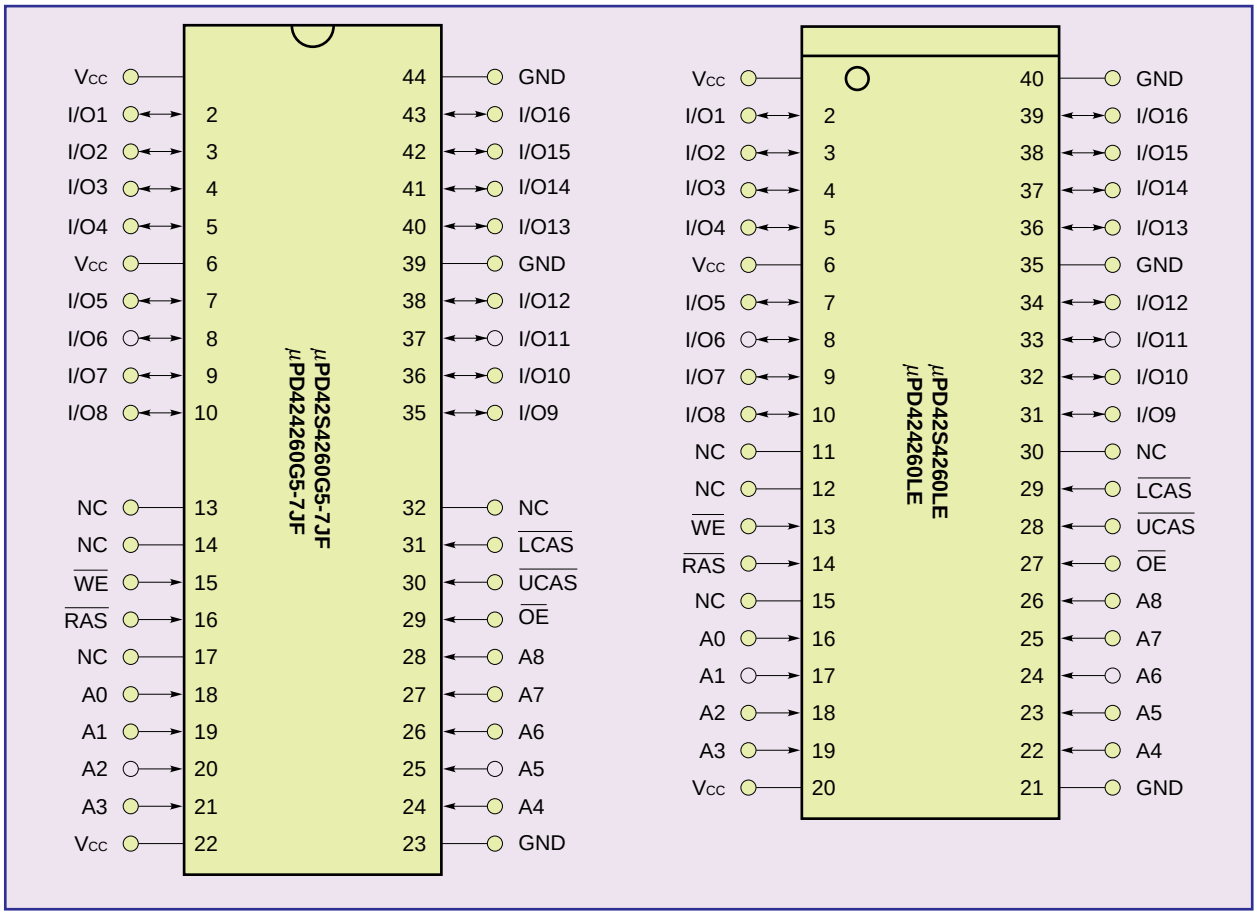
★ Ordering Information

Part number	Access time (MAX.)	Package	Refresh
μPD42S4260G5-60-7JF	60 ns	44-pin Plastic TSOP (II) (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ self refresh $\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD42S4260G5-70-7JF	70 ns		
μPD42S4260G5-80-7JF	80 ns		
μPD42S4260LE-60	60 ns	40-pin Plastic SOJ (400 mil)	
μPD42S4260LE-70	70 ns		
μPD42S4260LE-80	80 ns		
μPD424260G5-60-7JF	60 ns	44-pin Plastic TSOP (II) (400 mil)	$\overline{CAS}$ before $\overline{RAS}$ refresh $\overline{RAS}$ only refresh Hidden refresh
μPD424260G5-70-7JF	70 ns		
μPD424260G5-80-7JF	80 ns		
μPD424260LE-60	60 ns	40-pin Plastic SOJ (400 mil)	
μPD424260LE-70	70 ns		
μPD424260LE-80	80 ns		

Pin Configurations (Marking Side)

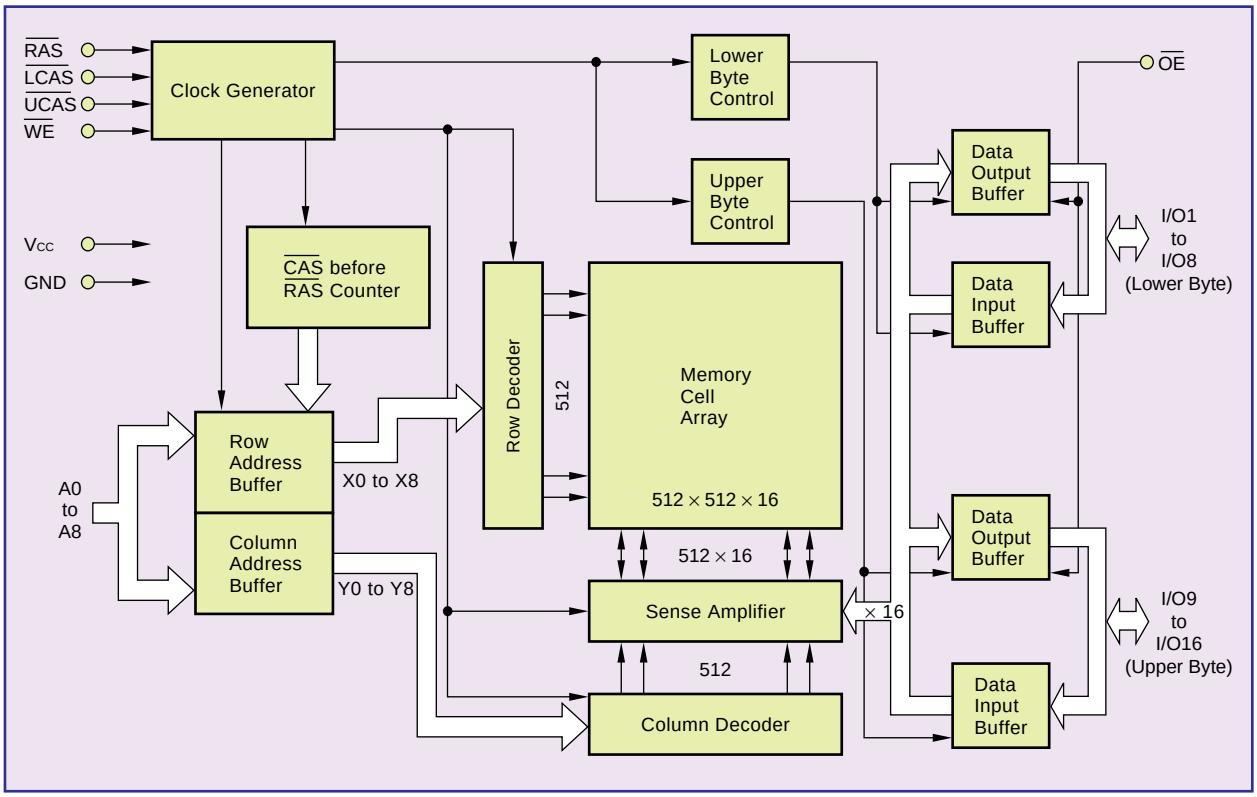
44-pin Plastic TSOP (II)
(400 mil)

40-pin Plastic SOJ
(400 mil)



A0 to A8	:	Address Inputs
I/O1 to I/O16	:	Data Inputs/Outputs
$\overline{RAS}$	:	Row Address Strobe
$\overline{UCAS}$	:	Column Address Strobe (upper)
$\overline{LCAS}$	:	Column Address Strobe (lower)
$\overline{WE}$	:	Write Enable
$\overline{OE}$	:	Output Enable
V_{CC}	:	Power Supply
GND	:	Ground
NC	:	No Connection

Block Diagram



Input/Output Pin Functions

The μPD42S4260, 424260 have input pins $\overline{RAS}$, $\overline{CAS}$[Note], $\overline{WE}$, $\overline{OE}$, A0 to A8 and input/output pins I/O1 to I/O16.

Pin name	Input/ Output	Function
$\overline{RAS}$ (Row address strobe)	Input	$\overline{RAS}$ activates the sense amplifier by latching a row address (A0 to A8) and selecting a corresponding word line. It refreshes memory cell array of one line selected by the row address (A0 to A8). It also selects the following function. • $\overline{CAS}$ before $\overline{RAS}$ refresh
$\overline{CAS}$ (Column address strobe)	Input	$\overline{CAS}$ activates data input/output circuit by latching column address (A0 to A8) and selecting a digit line connected with the sense amplifier.
A0 to A8 (Address input)	Input	9-bit address bus. Input total 18-bit of address signal, upper 9-bit and lower 9-bit in sequence (address multiplex method). Therefore, one word (16-bit) is selected from 262,144-word by 16-bit memory cell array. In actual operation, latch row address by specifying row address and activating $\overline{RAS}$. Then, switch the address bus to column address and activate $\overline{CAS}$. Each address is taken into the device when $\overline{RAS}$ and $\overline{CAS}$ are activated. Therefore, the address input setup time (t_{ASR}, t_{ASC}) and hold time (t_{RAH}, t_{CAH}) are specified for the activation of $\overline{RAS}$ and $\overline{CAS}$.
$\overline{WE}$ (Write enable)	Input	Write control signal. Write operation is executed by activating RAS, CAS and $\overline{WE}$.
$\overline{OE}$ (Output enable)	Input	Read control signal. Read operation can be executed by activating $\overline{RAS}$, $\overline{CAS}$ and $\overline{OE}$. If $\overline{WE}$ is activated during read operation, $\overline{OE}$ is to be ineffective in the device. Therefore, read operation cannot be executed.
I/O1 to I/O16 (Data input/ output)	Input/ Output	16-bit data bus. I/O1 to I/O16 are used to input/output data.

Note $\overline{CAS}$ means $\overline{UCAS}$ and $\overline{LCAS}$.

Electrical Specifications

- $\overline{CAS}$ means $\overline{UCAS}$ and $\overline{LCAS}$.
- All voltages are referenced to GND.
- After power up ($V_{CC} \geq V_{CC\ (MIN.)}$), wait more than 100 μs ($\overline{RAS}$, $\overline{CAS}$ inactive) and then, execute eight $\overline{CAS}$ before $\overline{RAS}$ or $\overline{RAS}$ only refresh cycles as dummy cycles to initialize internal circuit.

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Voltage on any pin relative to GND	V_T		–1.0 to +7.0	V
Supply voltage	V_{CC}		–1.0 to +7.0	V
Output current	I_O		50	mA
Power dissipation	P_D		1	W
Operating ambient temperature	T_A		0 to +70	˚C
Storage temperature	T_{stg}		–55 to +125	˚C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{CC}		4.5	5.0	5.5	V
High level input voltage	V_{IH}		2.4		V_{CC} +1.0	V
Low level input voltage	V_{IL}		–1.0		+0.8	V
Operating ambient temperature	T_A		0		70	˚C

Capacitance (T_A = 25 ˚C, f = 1 MHz)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{I1}	Address			5	pF
	C_{I2}	$\overline{RAS}$, $\overline{CAS}$, $\overline{WE}$, $\overline{OE}$			7	pF
Data input/output capacitance	$C_{I/O}$	I/O			7	pF

DC Characteristics (Recommended Operating Conditions unless otherwise noted)

	Parameter		Symbol	Test condition		MIN.	TYP.	MAX.	Unit	Notes
★	Operating current		I_{CC1}	$\overline{RAS}$, $\overline{CAS}$ cycling $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns			160	mA	1, 2, 3
					t_{RAC} = 70 ns			160		
					t_{RAC} = 80 ns			145		
	Standby current	μPD42S4260	I_{CC2}	$\overline{RAS}$, $\overline{CAS}$ ≥ $V_{IH\ (MIN.)}$, I_O = 0 mA				2	mA	
				$\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V, I_O = 0 mA				0.15		
		μPD424260		$\overline{RAS}$, $\overline{CAS}$ ≥ $V_{IH\ (MIN.)}$, I_O = 0 mA				2		
				$\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V, I_O = 0 mA				1		
★	$\overline{RAS}$ only refresh current		I_{CC3}	$\overline{RAS}$ cycling, $\overline{CAS}$ ≥ $V_{IH\ (MIN.)}$ $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns			160	mA	1, 2, 3, 4
					t_{RAC} = 70 ns			160		
					t_{RAC} = 80 ns			145		
★	Operating current (Fast page mode)		I_{CC4}	$\overline{RAS}$ ≤ $V_{IL\ (MAX.)}$, $\overline{CAS}$ cycling $t_{PC} = t_{PC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns			140	mA	1, 2, 5
					t_{RAC} = 70 ns			140		
					t_{RAC} = 80 ns			130		
★	$\overline{CAS}$ before $\overline{RAS}$ refresh current		I_{CC5}	$\overline{RAS}$ cycling $t_{RC} = t_{RC\ (MIN.)}$, I_O = 0 mA	t_{RAC} = 60 ns			160	mA	1, 2
					t_{RAC} = 70 ns			160		
					t_{RAC} = 80 ns			145		
	$\overline{CAS}$ before $\overline{RAS}$ long refresh current (512 cycles / 128 ms, only for the μPD42S4260)		I_{CC6}	$\overline{CAS}$ before $\overline{RAS}$ refresh: t_{RC} = 250.0 μs $\overline{RAS}$, $\overline{CAS}$: V_{CC} – 0.2 V ≤ V_{IH} ≤ $V_{IH(MAX.)}$ 0 V ≤ V_{IL} ≤ 0.2 V	t_{RAS} ≤ 200 ns			200	μA	1, 2
				Standby: $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} – 0.2 V Address: V_{IH} or V_{IL} $\overline{WE}$, $\overline{OE}$: V_{IH} I_O = 0 mA	t_{RAS} ≤ 1 μs			300	μA	1, 2
	Self refresh current ($\overline{CAS}$ before $\overline{RAS}$ self refresh, only for the μPD42S4260)		I_{CC7}	$\overline{RAS}$, $\overline{CAS}$: t_{RASS} = 5 ms V_{CC} – 0.2 V ≤ V_{IH} ≤ $V_{IH\ (MAX.)}$ 0 V ≤ V_{IL} ≤ 0.2 V I_O = 0 mA				150	μA	2
	Input leakage current		$I_{I(L)}$	V_I = 0 to 5.5 V All other pins not under test = 0 V		–10		+10	μA	
	Output leakage current		$I_{O(L)}$	V_O = 0 to 5.5 V Output is disabled (Hi-Z)		–10		+10	μA	
	High level output voltage		V_{OH}	I_O = –2.5 mA		2.4			V	
	Low level output voltage		V_{OL}	I_O = +2.1 mA				0.4	V	

Notes 1. I_{CC1}, I_{CC3}, I_{CC4}, I_{CC5} and I_{CC6} depend on cycle rates (t_{RC} and t_{PC}).

2. Specified values are obtained with outputs unloaded.

3. I_{CC1} and I_{CC3} are measured assuming that address can be changed once or less during $\overline{RAS}$ ≤ $V_{IL\ (MAX.)}$ and $\overline{CAS}$ ≥ $V_{IH\ (MIN.)}$.

4. I_{CC3} is measured assuming that all column address inputs are held at either high or low.

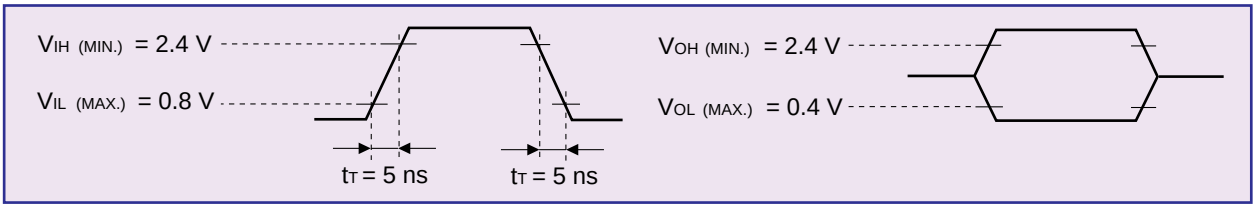
5. I_{CC4} is measured assuming that all column address inputs are switched only once during each fast page cycle.

★ AC Characteristics (Recommended Operating Conditions unless otherwise noted)

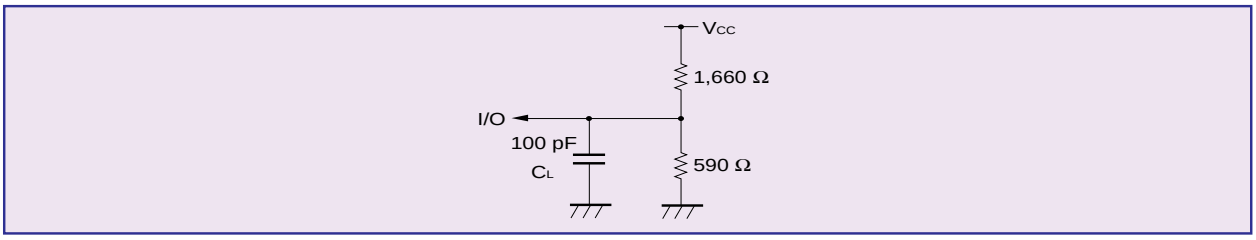
AC Characteristics Test Conditions

(1) Input timing specification

(2) Output timing specification



(3) Output load condition



Common to Read, Write, Read Modify Write Cycle

Parameter		Symbol	tRAC = 60 ns		tRAC = 70 ns		tRAC = 80 ns		Unit	Notes
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read/Write cycle time		tRC	110	–	130	–	150	–	ns	
$\overline{RAS}$ precharge time		tRP	40	–	50	–	60	–	ns	
$\overline{CAS}$ precharge time		tCPN	10	–	10	–	10	–	ns	
$\overline{RAS}$ pulse width		tRAS	60	10,000	70	10,000	80	10,000	ns	1
$\overline{CAS}$ pulse width		tCAS	15	10,000	20	10,000	20	10,000	ns	
$\overline{RAS}$ hold time		tRSH	15	–	20	–	20	–	ns	
$\overline{CAS}$ hold time		tCSH	60	–	70	–	80	–	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time		tRCD	20	45	20	50	20	60	ns	2
$\overline{RAS}$ to column address delay time		tRAD	15	30	15	35	15	40	ns	2
$\overline{CAS}$ to $\overline{RAS}$ precharge time		tCRP	10	–	10	–	10	–	ns	3
Row address setup time		tASR	0	–	0	–	0	–	ns	
Row address hold time		tRAH	10	–	10	–	10	–	ns	
Column address setup time		tASC	0	–	0	–	0	–	ns	
Column address hold time		tCAH	15	–	15	–	15	–	ns	
$\overline{OE}$ lead time referenced to $\overline{RAS}$		tOES	0	–	0	–	0	–	ns	
$\overline{CAS}$ to data setup time		tCLZ	0	–	0	–	0	–	ns	
$\overline{OE}$ to data setup time		tOLZ	0	–	0	–	0	–	ns	
$\overline{OE}$ to data delay time		tOED	15	–	15	–	20	–	ns	
Masked byte write hold time referenced to $\overline{RAS}$		tMRH	0	–	0	–	0	–	ns	
Transition time (rise and fall)		tT	3	50	3	50	3	50	ns	
Refresh time	μPD42S4260	tREF	–	128	–	128	–	128	ms	4
	μPD424260		–	8	–	8	–	8	ms	

Notes 1. In $\overline{CAS}$ before $\overline{RAS}$ refresh cycles, $t_{RAS\ (MAX.)}$ is 100 μs.
If 10 μs < t_{RAS} < 100 μs, $\overline{RAS}$ precharge time for $\overline{CAS}$ before $\overline{RAS}$ self refresh (t_{RPS}) is applied.

2. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from $\overline{RAS}$
$t_{RAD} \leq t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD\ (MAX.)}$ and $t_{RCD\ (MAX.)}$ are specified as reference points only; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD\ (MAX.)}$ and $t_{RCD} \geq t_{RCD\ (MAX.)}$ will not cause any operation problems.

3. $t_{CRP\ (MIN.)}$ requirement is applied to $\overline{RAS}$, $\overline{CAS}$ cycles.

4. This specification is applied only to the μPD42S4260.

Read Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Access time from $\overline{RAS}$	t_{RAC}	–	60	–	70	–	80	ns	1
Access time from $\overline{CAS}$	t_{CAC}	–	15	–	20	–	20	ns	1
Access time from column address	t_{AA}	–	30	–	35	–	40	ns	1
Access time from $\overline{OE}$	t_{OEA}	–	15	–	20	–	20	ns	
Column address lead time referenced to $\overline{RAS}$	t_{RAL}	30	–	35	–	40	–	ns	
Read command setup time	t_{RCS}	0	–	0	–	0	–	ns	
Read command hold time referenced to $\overline{RAS}$	t_{RRH}	0	–	0	–	0	–	ns	2
Read command hold time referenced to $\overline{CAS}$	t_{RCH}	0	–	0	–	0	–	ns	2
Output buffer turn-off delay time from $\overline{OE}$	t_{OEZ}	0	15	0	15	0	20	ns	3
Output buffer turn-off delay time from $\overline{CAS}$	t_{OFF}	0	15	0	15	0	20	ns	3

Notes 1. For read cycles, access time is defined as follows:

Input conditions	Access time	Access time from $\overline{RAS}$
$t_{RAD} \leq t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{RAC\ (MAX.)}$	$t_{RAC\ (MAX.)}$
$t_{RAD} > t_{RAD\ (MAX.)}$ and $t_{RCD} \leq t_{RCD\ (MAX.)}$	$t_{AA\ (MAX.)}$	$t_{RAD} + t_{AA\ (MAX.)}$
$t_{RCD} > t_{RCD\ (MAX.)}$	$t_{CAC\ (MAX.)}$	$t_{RCD} + t_{CAC\ (MAX.)}$

$t_{RAD\ (MAX.)}$ and $t_{RCD\ (MAX.)}$ are specified as reference points only; they are not restrictive operating parameters. They are used to determine which access time (t_{RAC}, t_{AA} or t_{CAC}) is to be used for finding out when output data will be available. Therefore, the input conditions $t_{RAD} \geq t_{RAD\ (MAX.)}$ and $t_{RCD} \geq t_{RCD\ (MAX.)}$ will not cause any operation problems.

2. Either $t_{RCH\ (MIN.)}$ or $t_{RRH\ (MIN.)}$ should be met in read cycles.

3. $t_{OFF\ (MAX.)}$ and $t_{OEZ\ (MAX.)}$ define the time when the output achieves the condition of Hi-Z and is not referenced to V_{OH} or V_{OL}.

Write Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
$\overline{WE}$ hold time referenced to $\overline{CAS}$	t_{WCH}	15	–	15	–	15	–	ns	1
$\overline{WE}$ pulse width	t_{WP}	10	–	15	–	15	–	ns	1
$\overline{WE}$ lead time referenced to $\overline{RAS}$	t_{RWL}	15	–	20	–	20	–	ns	
$\overline{WE}$ lead time referenced to $\overline{CAS}$	t_{CWL}	15	–	15	–	20	–	ns	
$\overline{WE}$ setup time	t_{WCS}	0	–	0	–	0	–	ns	2
$\overline{OE}$ hold time	t_{OEH}	0	–	0	–	0	–	ns	
Data-in setup time	t_{DS}	0	–	0	–	0	–	ns	3
Data-in hold time	t_{DH}	15	–	15	–	20	–	ns	3

Notes 1. $t_{WP\ (MIN.)}$ is applied to late write cycles or read modify write cycles. In early write cycles, $t_{WCH\ (MIN.)}$ should be met.

2. If $t_{WCS} \geq t_{WCS\ (MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle.

3. $t_{DS\ (MIN.)}$ and $t_{DH\ (MIN.)}$ are referenced to the $\overline{CAS}$ falling edge in early write cycles. In late write cycles and read modify write cycles, they are referenced to the $\overline{WE}$ falling edge.

Read Modify Write Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read modify write cycle time	t_{RWC}	150	–	175	–	200	–	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	80	–	90	–	105	–	ns	1
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	35	–	40	–	45	–	ns	1
Column address to $\overline{WE}$ delay time	t_{AWD}	50	–	55	–	65	–	ns	1

Note 1. If $t_{WCS} \geq t_{WCS\ (MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geq t_{RWD\ (MIN.)}$, $t_{CWD} \geq t_{CWD\ (MIN.)}$, $t_{AWD} \geq t_{AWD\ (MIN.)}$ and $t_{CPWD} \geq t_{CPWD\ (MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Fast Page Mode

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Fast page mode cycle time	t_{PC}	40	–	45	–	50	–	ns	
Access time from $\overline{CAS}$ precharge	t_{ACP}	–	35	–	40	–	45	ns	
$\overline{RAS}$ pulse width	t_{RASP}	60	125,000	70	125,000	80	125,000	ns	
$\overline{CAS}$ precharge time	t_{CP}	10	–	10	–	10	–	ns	
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{RHCP}	35	–	40	–	45	–	ns	
Read modify write cycle time	t_{PRWC}	80	–	85	–	100	–	ns	
$\overline{CAS}$ precharge to $\overline{WE}$ delay time	t_{CPWD}	55	–	60	–	70	–	ns	1

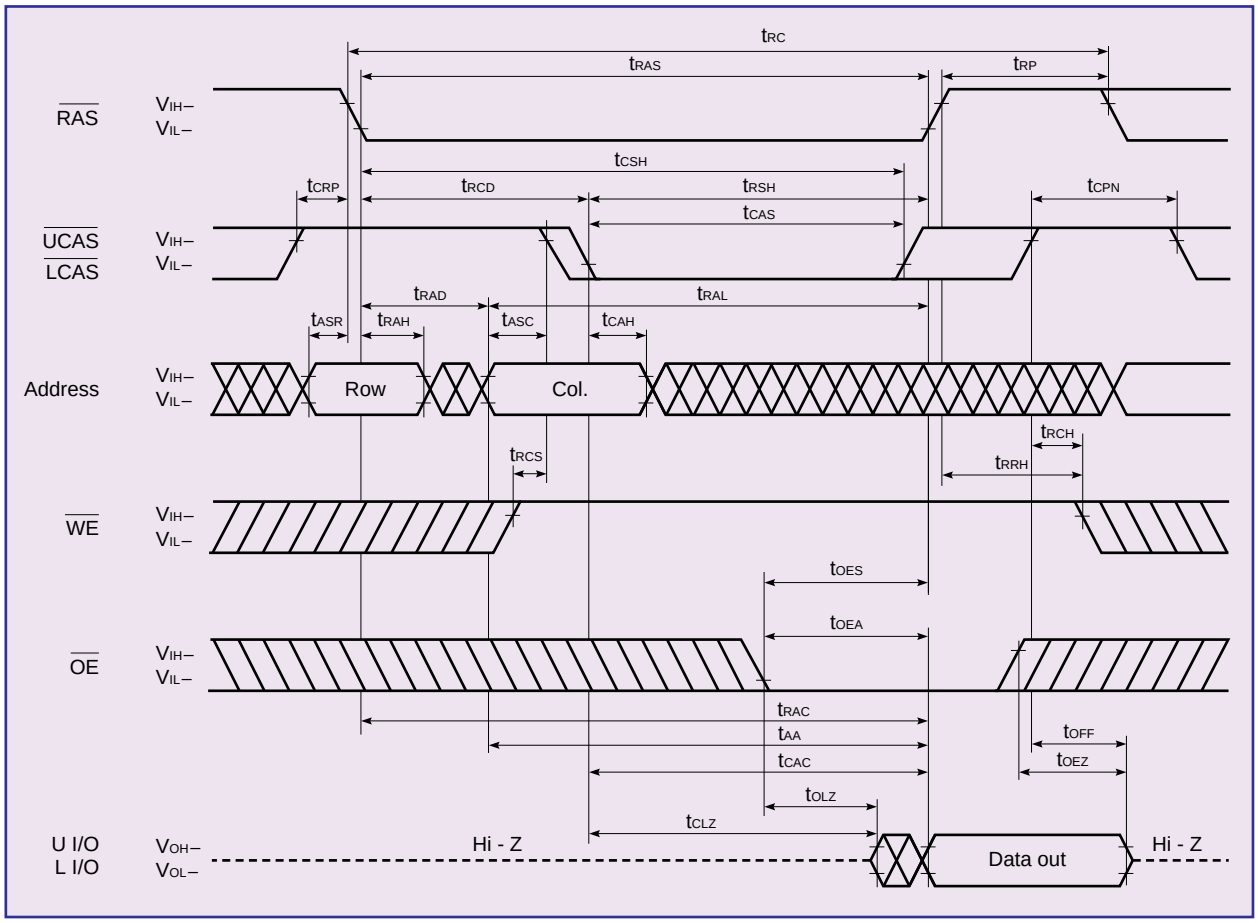
Note 1. If $t_{WCS} \geq t_{WCS\,(MIN.)}$, the cycle is an early write cycle and the data out will remain Hi-Z through the entire cycle. If $t_{RWD} \geq t_{RWD\,(MIN.)}$, $t_{CWD} \geq t_{CWD\,(MIN.)}$, $t_{AWD} \geq t_{AWD\,(MIN.)}$ and $t_{CPWD} \geq t_{CPWD\,(MIN.)}$, the cycle is a read modify write cycle and the data out will contain data read from the selected cell. If neither of the above conditions is met, the state of the data out is indeterminate.

Refresh Cycle

Parameter	Symbol	t_{RAC} = 60 ns		t_{RAC} = 70 ns		t_{RAC} = 80 ns		Unit	Note
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
$\overline{CAS}$ setup time	t_{CSR}	10	–	10	–	10	–	ns	
$\overline{CAS}$ hold time ($\overline{CAS}$ before $\overline{RAS}$ refresh)	t_{CHR}	10	–	15	–	15	–	ns	
$\overline{RAS}$ precharge $\overline{CAS}$ hold time	t_{RPC}	10	–	10	–	10	–	ns	
$\overline{RAS}$ pulse width ($\overline{CAS}$ before $\overline{RAS}$ self refresh cycle)	t_{RASS}	100	–	100	–	100	–	μs	1
$\overline{RAS}$ precharge time ($\overline{CAS}$ before $\overline{RAS}$ self refresh cycle)	t_{RPS}	110	–	130	–	150	–	ns	1
$\overline{CAS}$ hold time ($\overline{CAS}$ before $\overline{RAS}$ self refresh cycle)	t_{CHS}	–50	–	–50	–	–50	–	ns	1
$\overline{WE}$ hold time (hidden refresh cycle)	t_{WHR}	10	–	15	–	15	–	ns	

Note 1. This specification is applied only to the μPD42S4260.

Read Cycle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tRAS
tRP
RAS
VIH–
VIL–
tCSH
tCRP
tRCD
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tCPN
tCAS
UCAS
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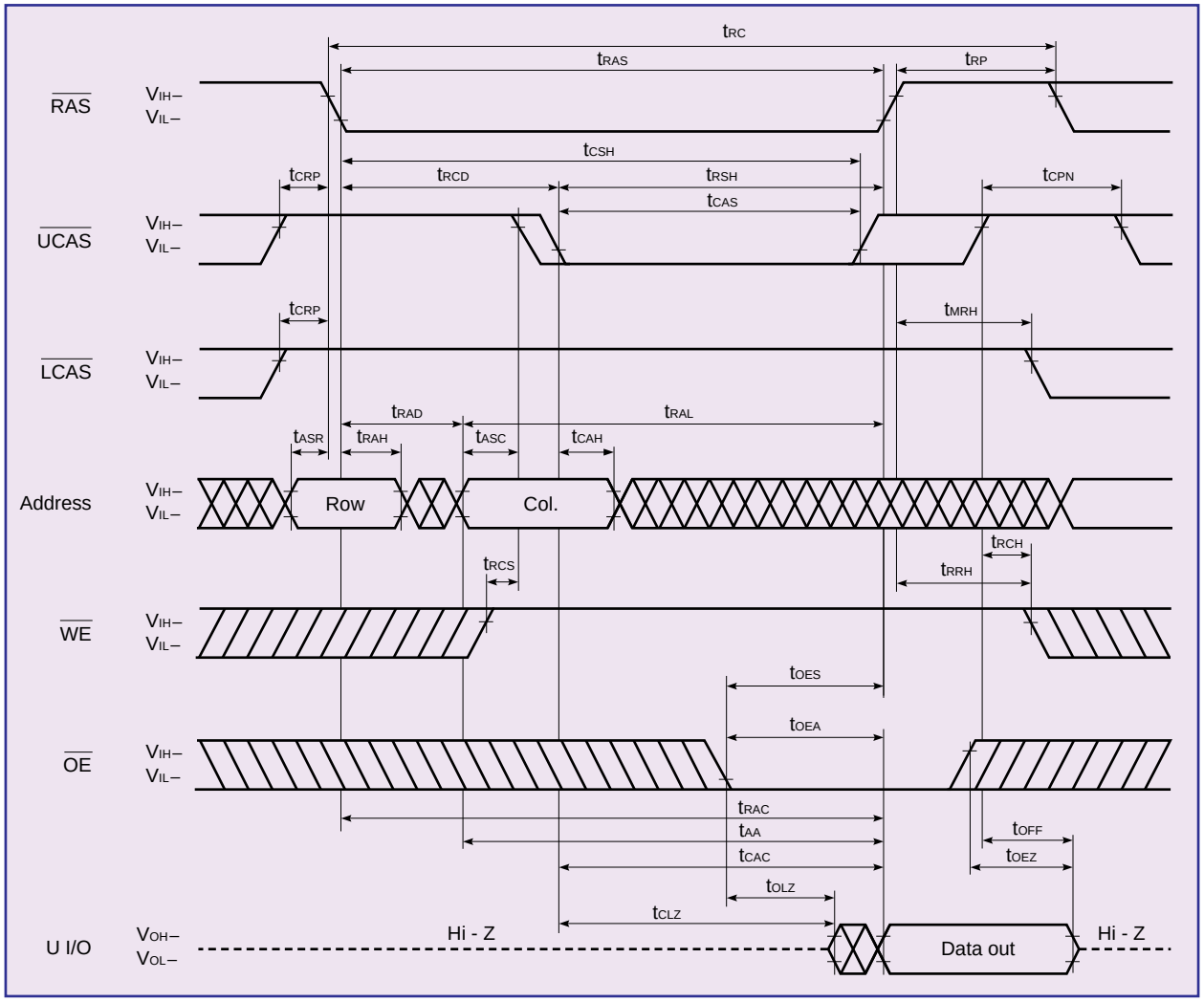
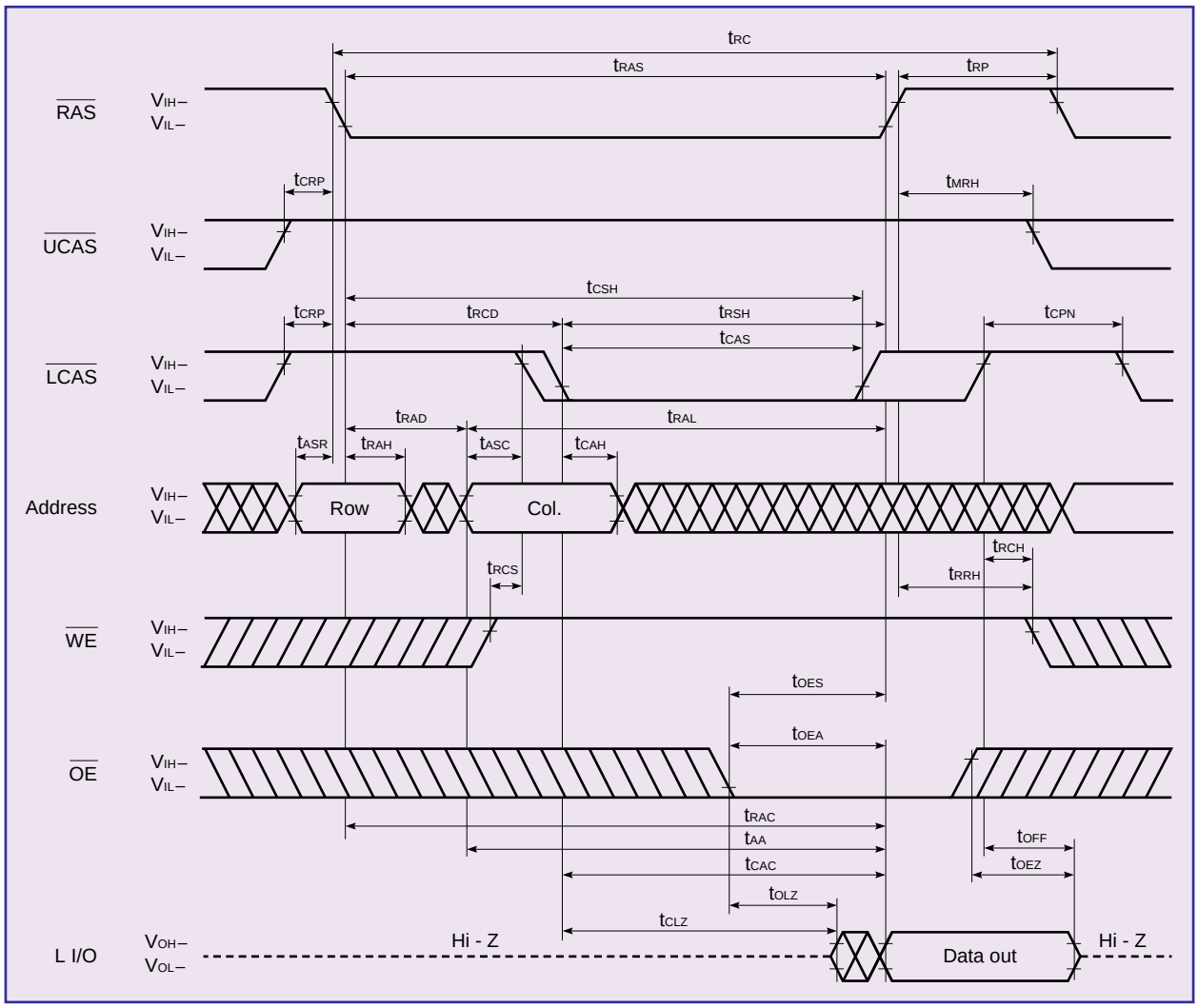
tRCS
tRRH
WE
tOES
tOEA
OE
tRAC
tAA
tOFF
tCAC
tOEZ
tOLZ
tCLZ
U I/O
L I/O
VOH–
VOL–
Hi - Z
Data out
Hi - Z

Upper Byte Read Cycle



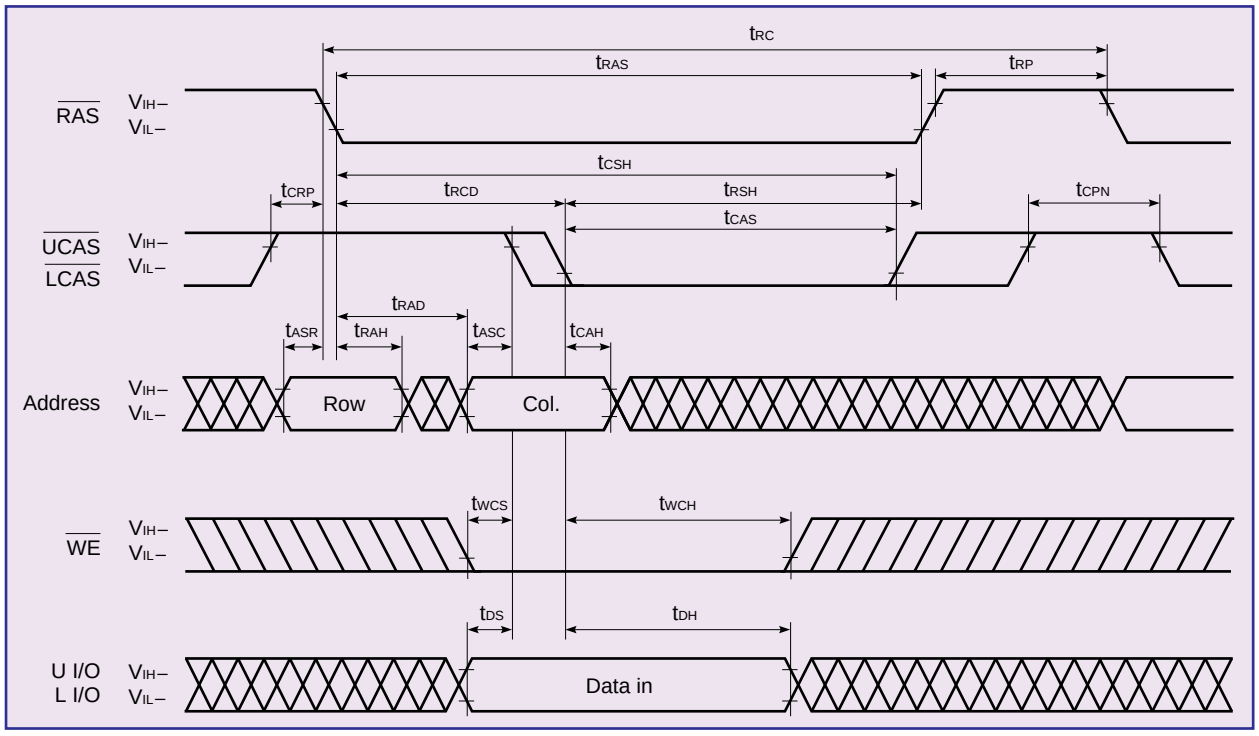
Remark L I/O: Hi-Z

Lower Byte Read Cycle



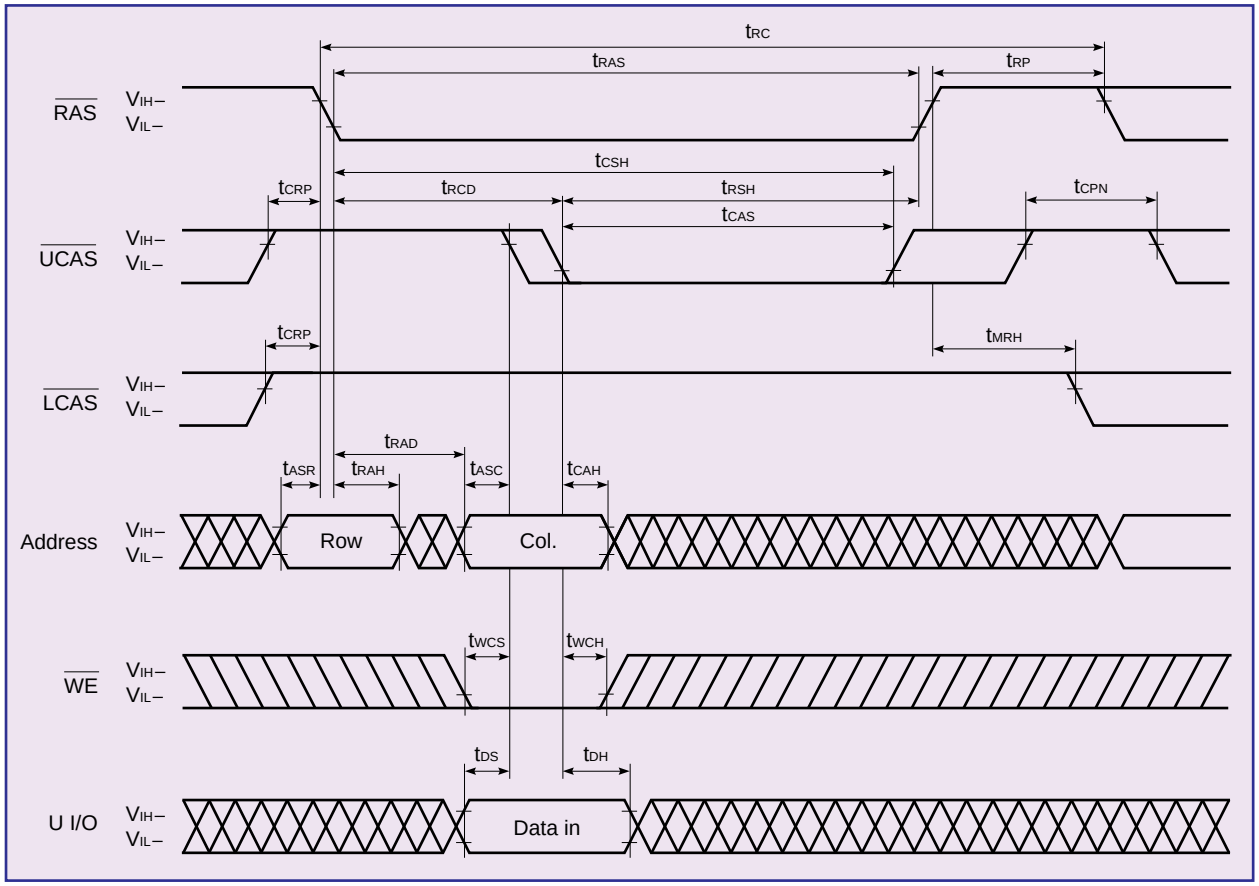
Remark U I/O: Hi-Z

Early Write Cycle



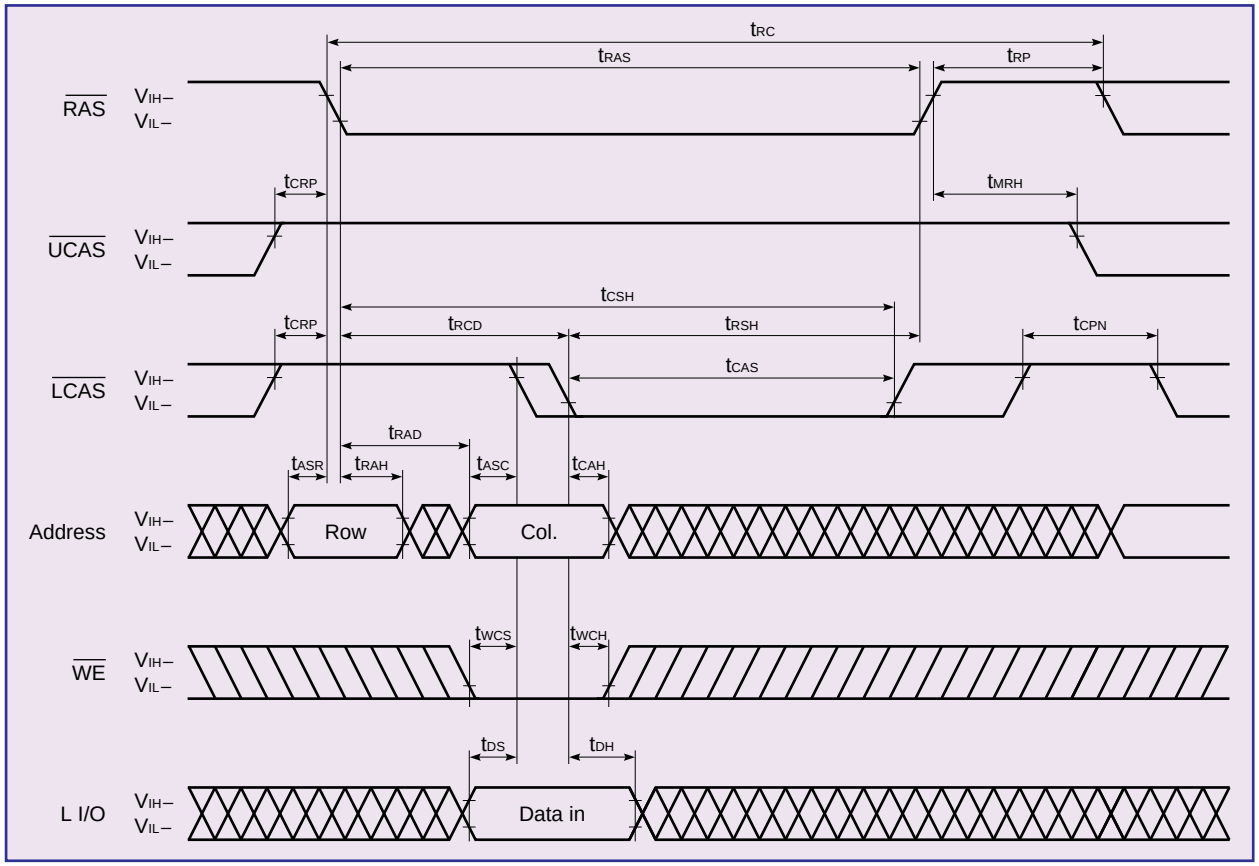
Remark $\overline{OE}$: Don't care

Upper Byte Early Write Cycle



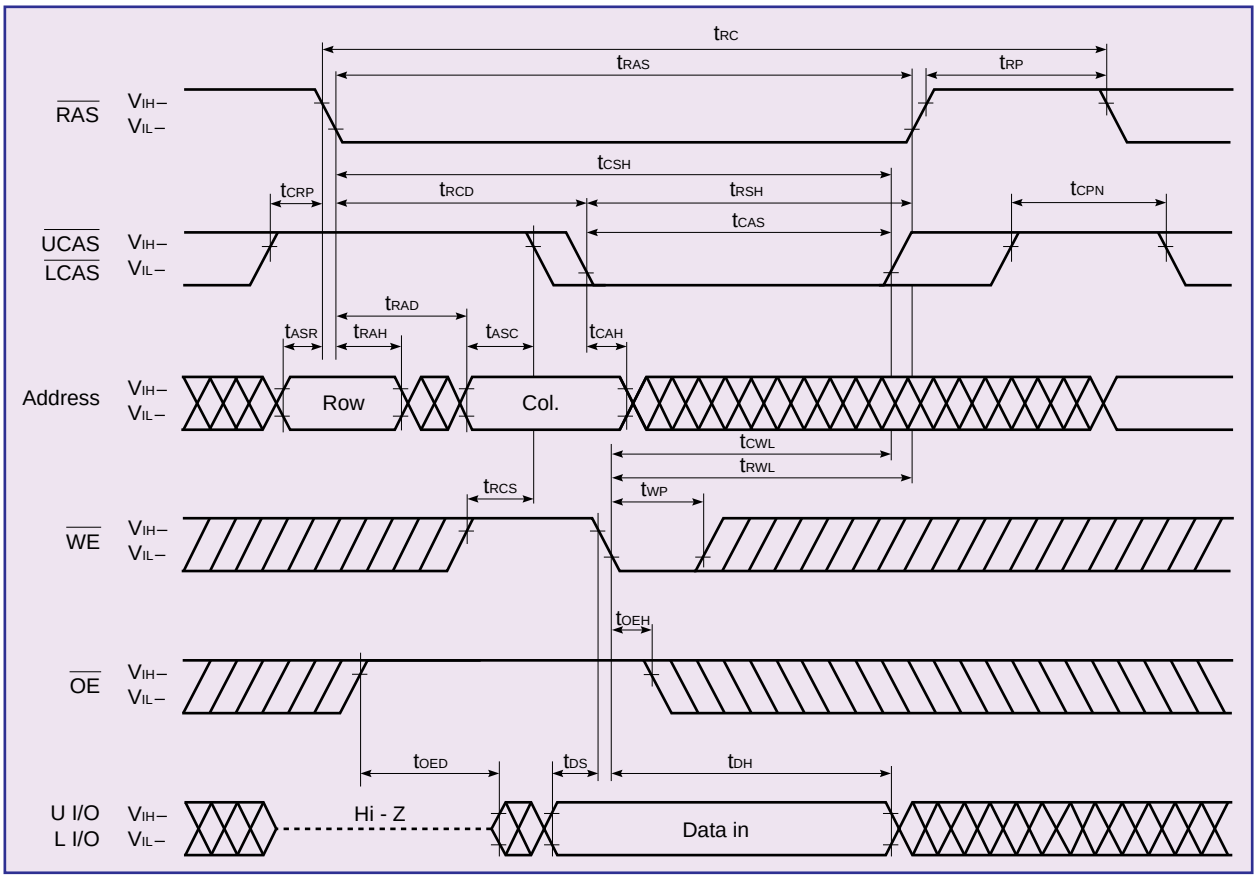
Remark $\overline{OE}$, L I/O: Don't care

Lower Byte Early Write Cycle

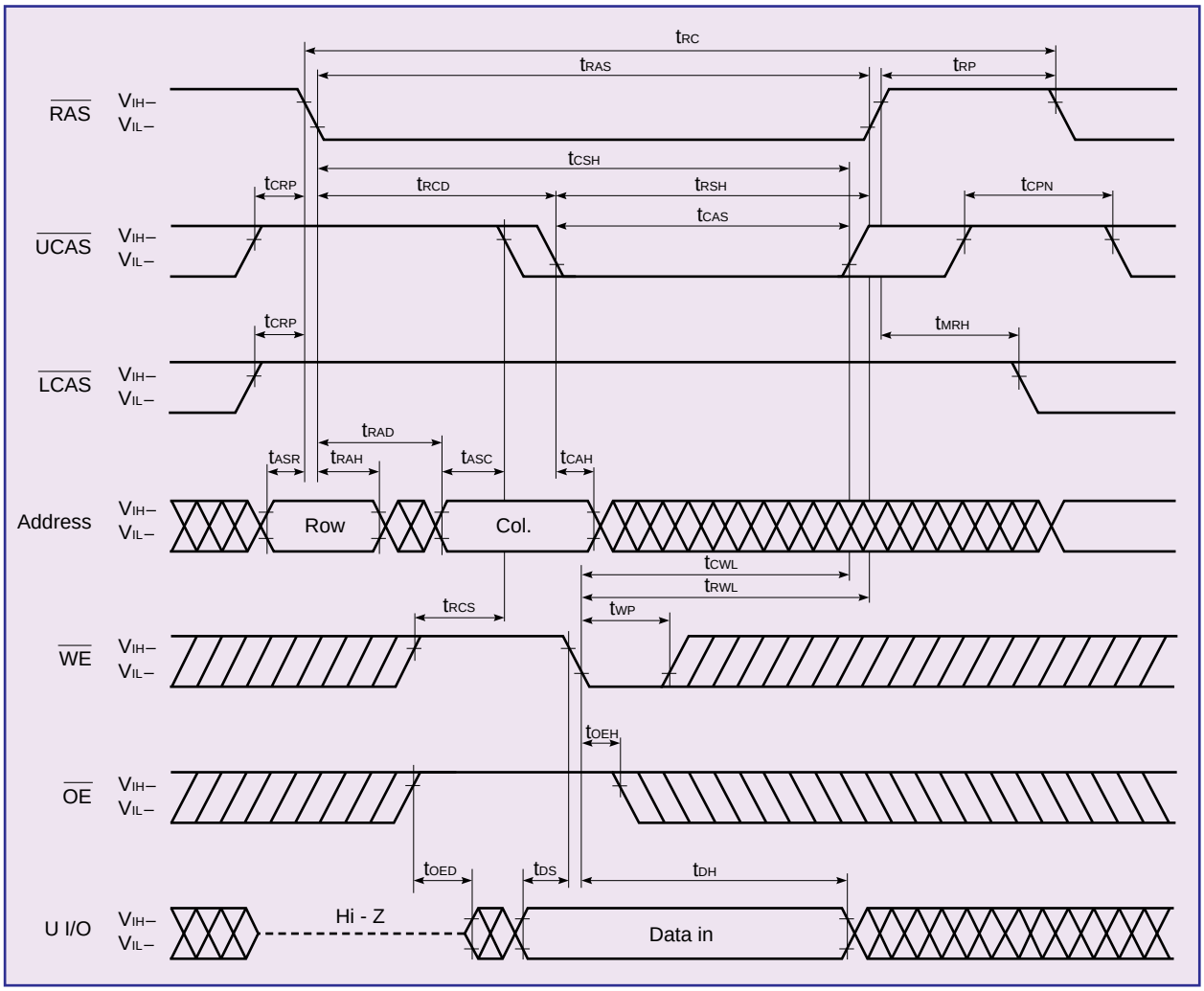


Remark $\overline{OE}$, U I/O: Don't care

Late Write Cycle

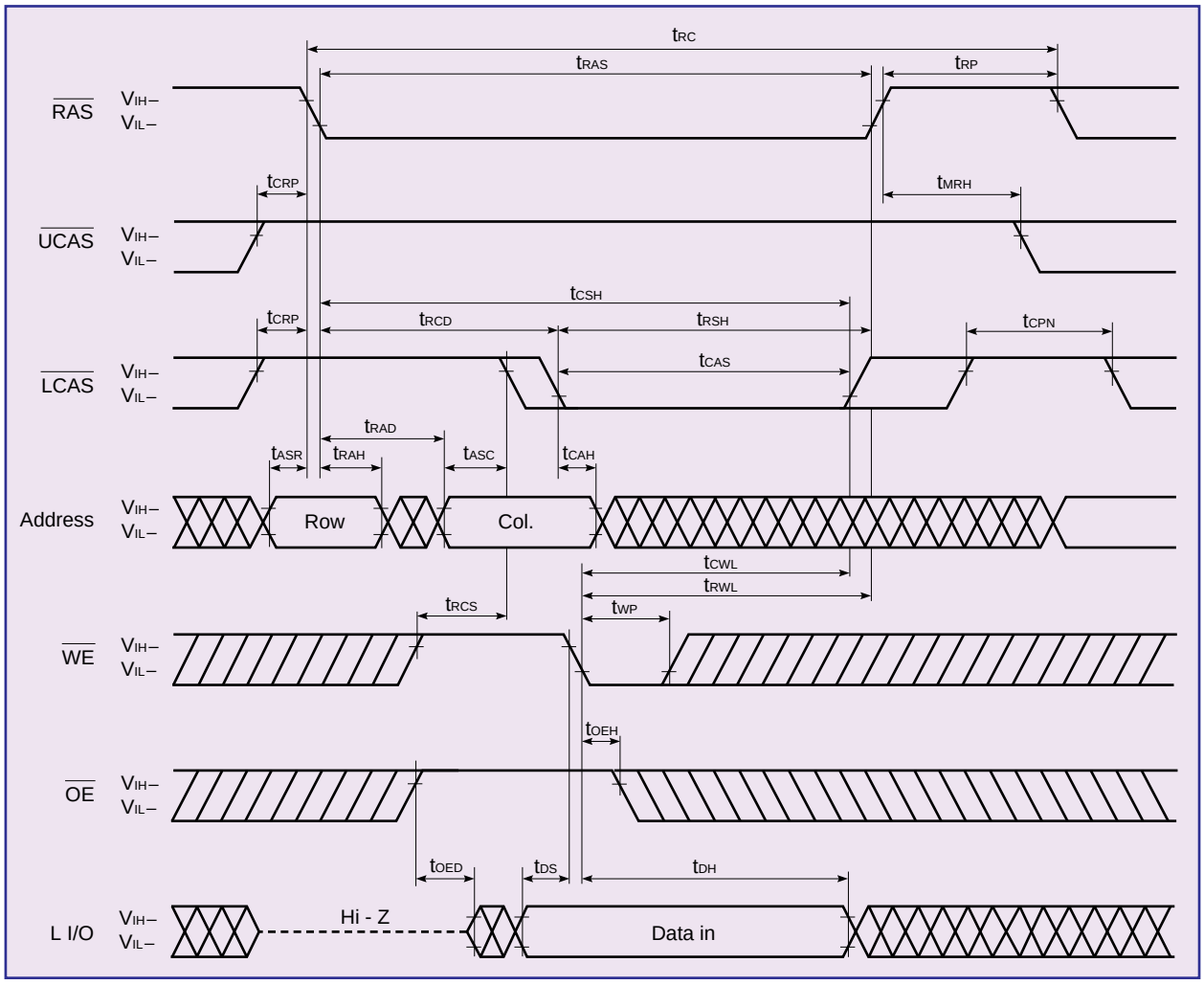


Upper Byte Late Write Cycle



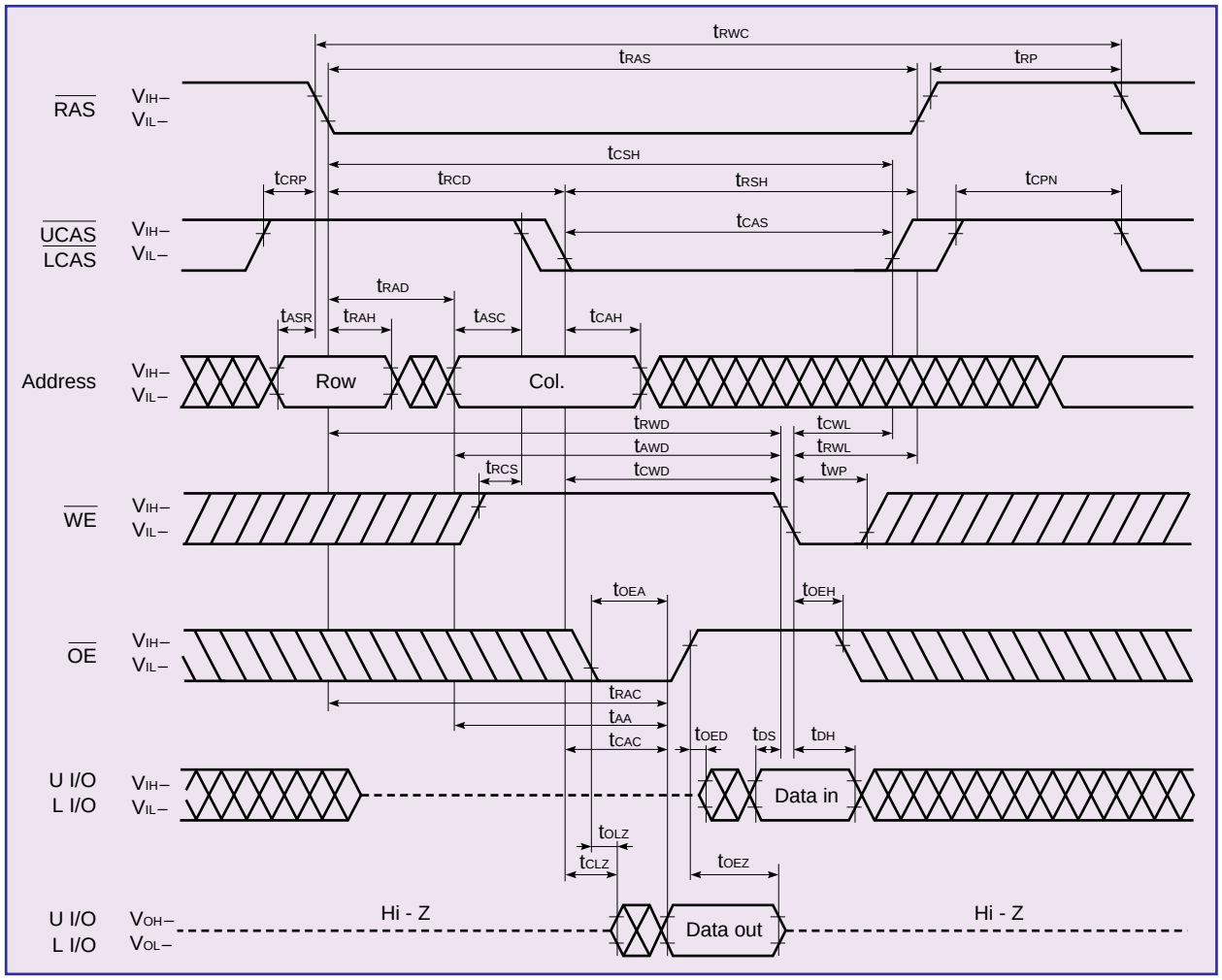
Remark L I/O: Don't care

Lower Byte Late Write Cycle

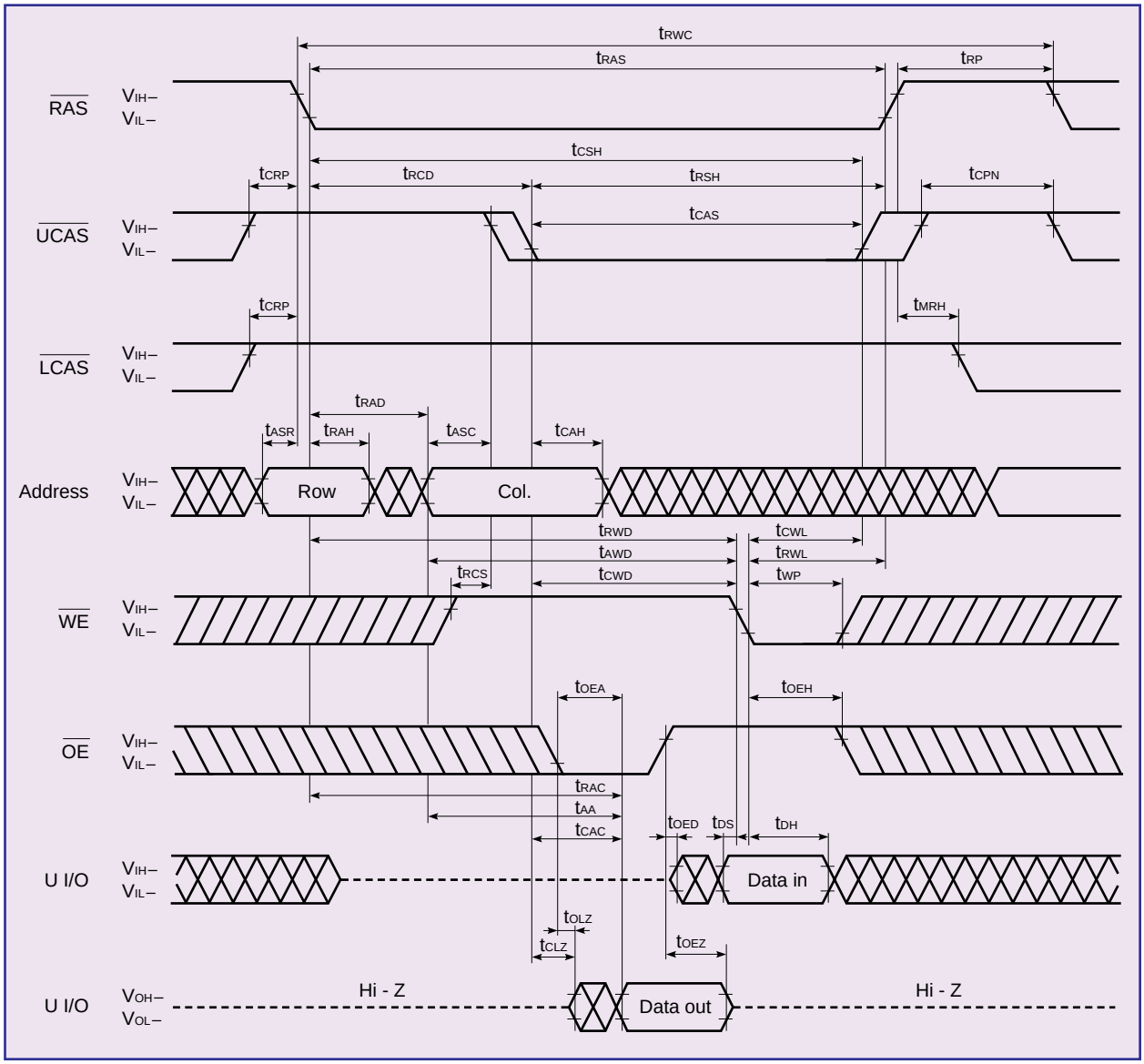


Remark U I/O: Don't care

Read Modify Write Cycle

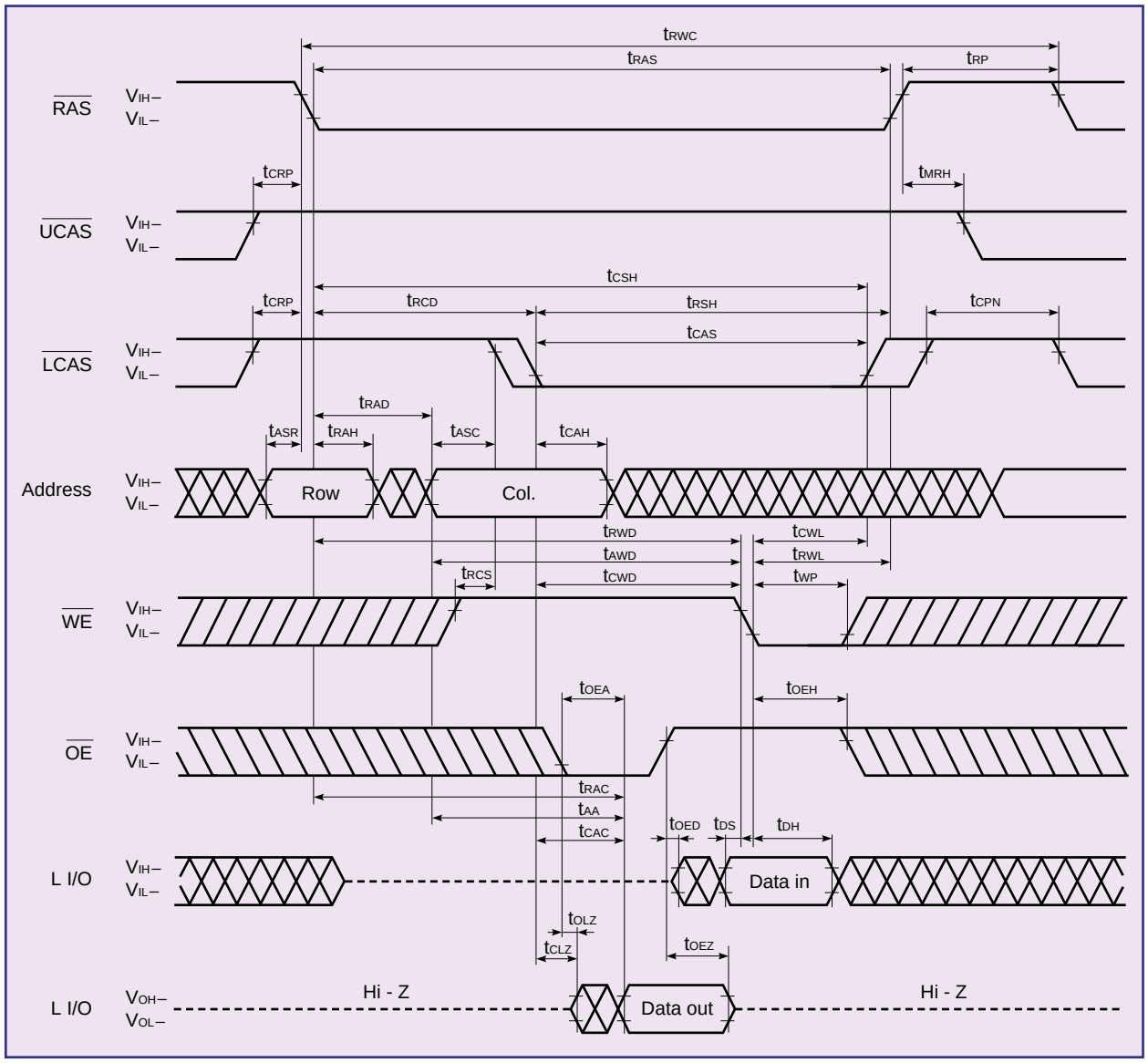


Upper Byte Read Modify Write Cycle



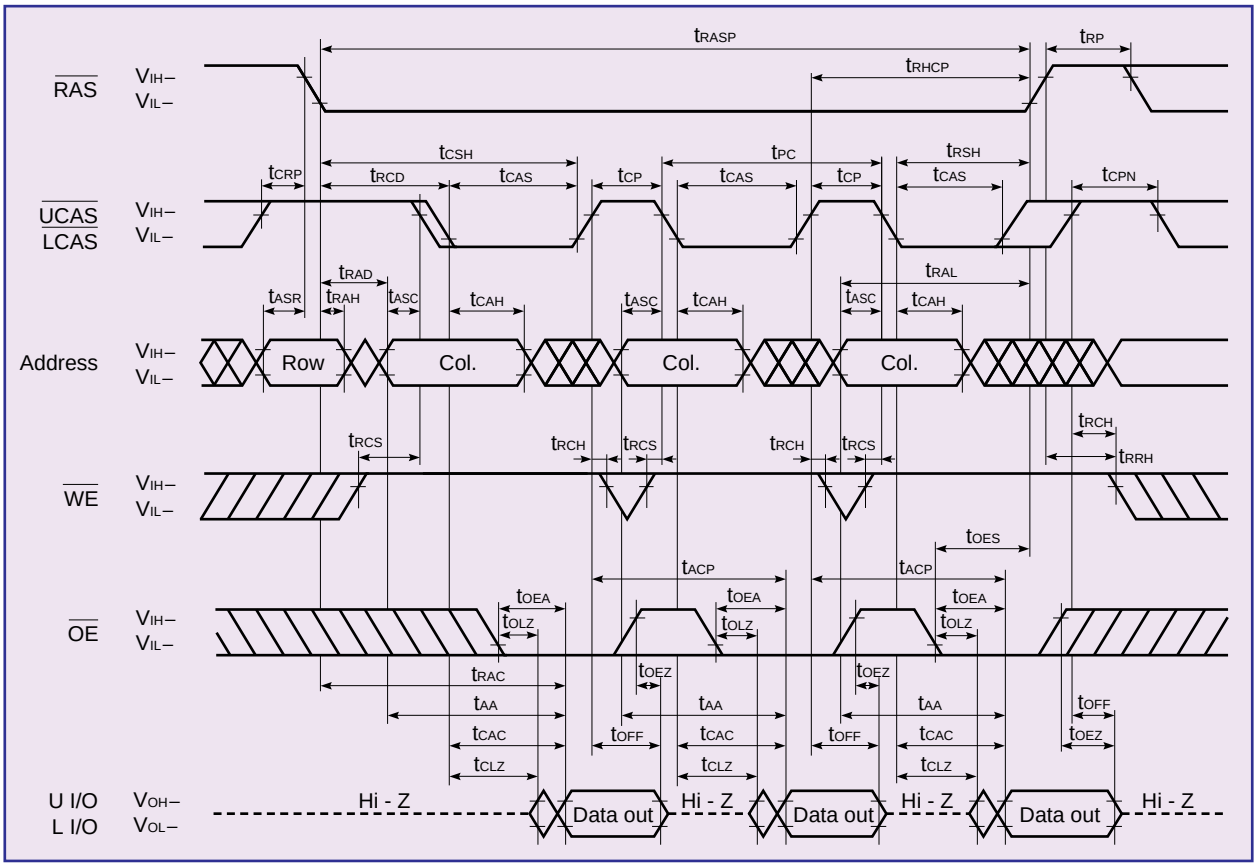
Remark In this cycle, the input data to Lower I/O is ineffective. The data out of that remains Hi-Z.

Lower Byte Read Modify Write Cycle



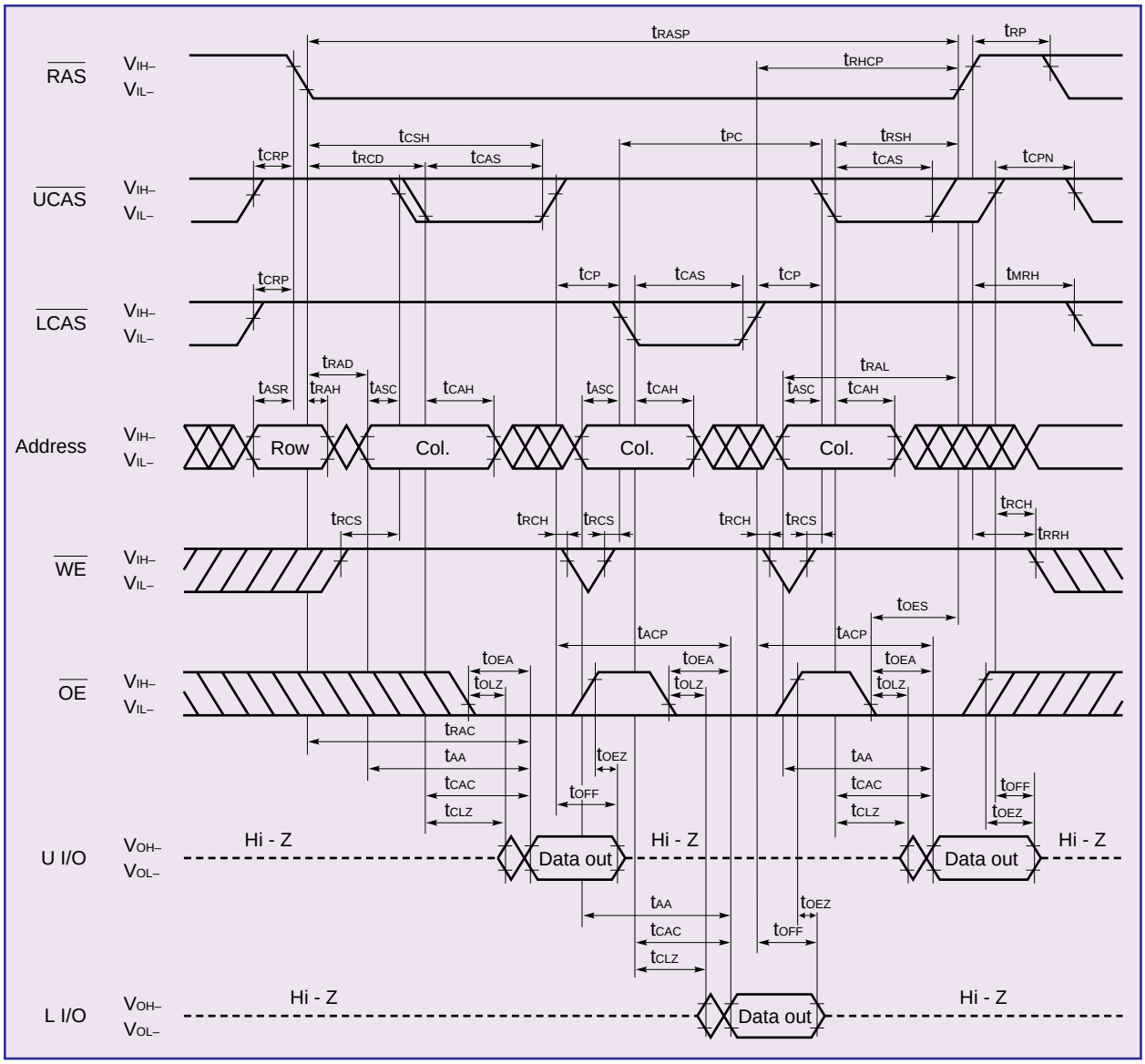
Remark In this cycle, the input data to Upper I/O is ineffective. The data out of that remains Hi-Z.

Fast Page Mode Read Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

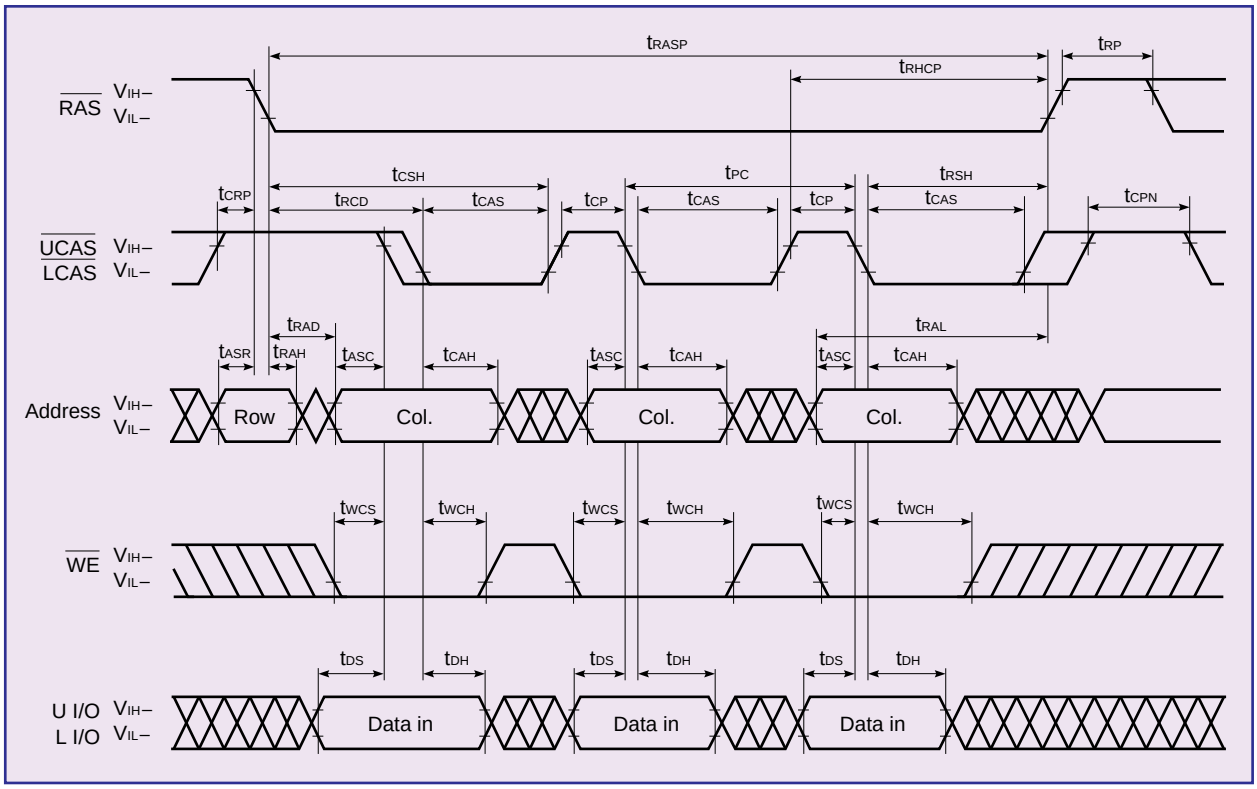
Fast Page Mode Byte Read Cycle



Remarks 1. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

2. This cycle can be used to control either $\overline{UCAS}$ or $\overline{LCAS}$ only. Or, it can be used to control $\overline{UCAS}$ or $\overline{LCAS}$ simultaneously, or at random.

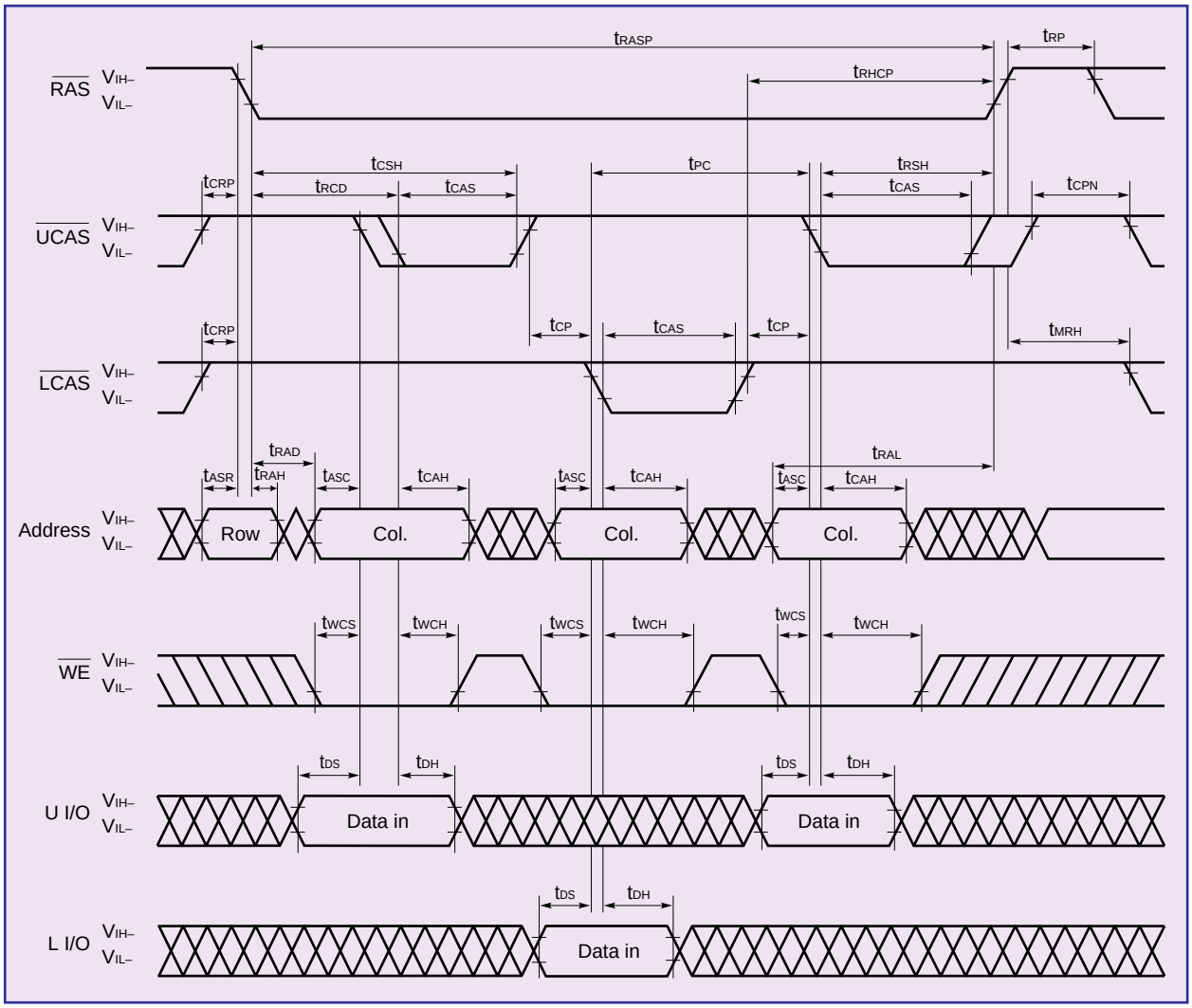
Fast Page Mode Early Write Cycle



Remarks 1. $\overline{OE}$: Don't care

2. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

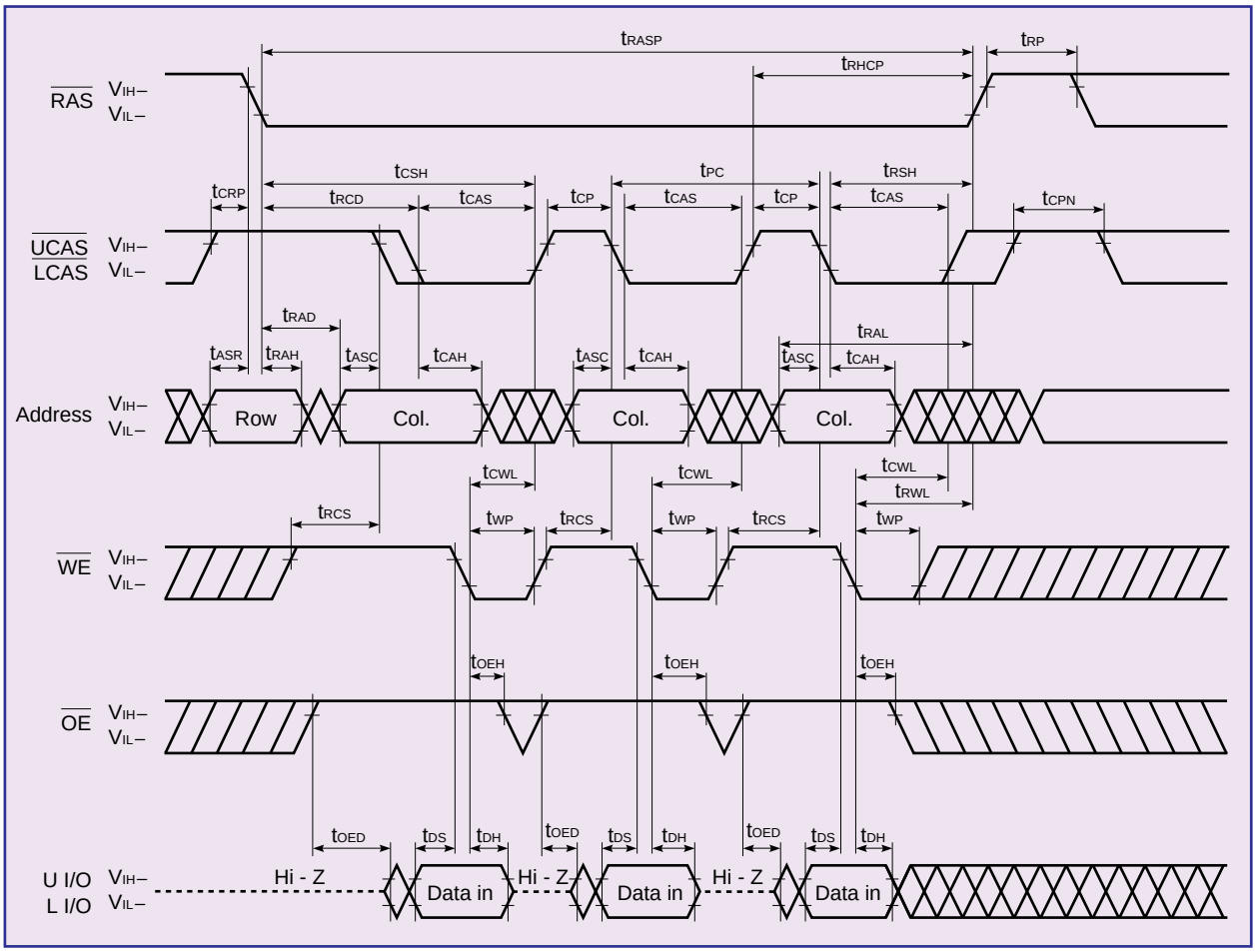
Fast Page Mode Byte Early Write Cycle



Remarks 1. $\overline{OE}$: Don't care

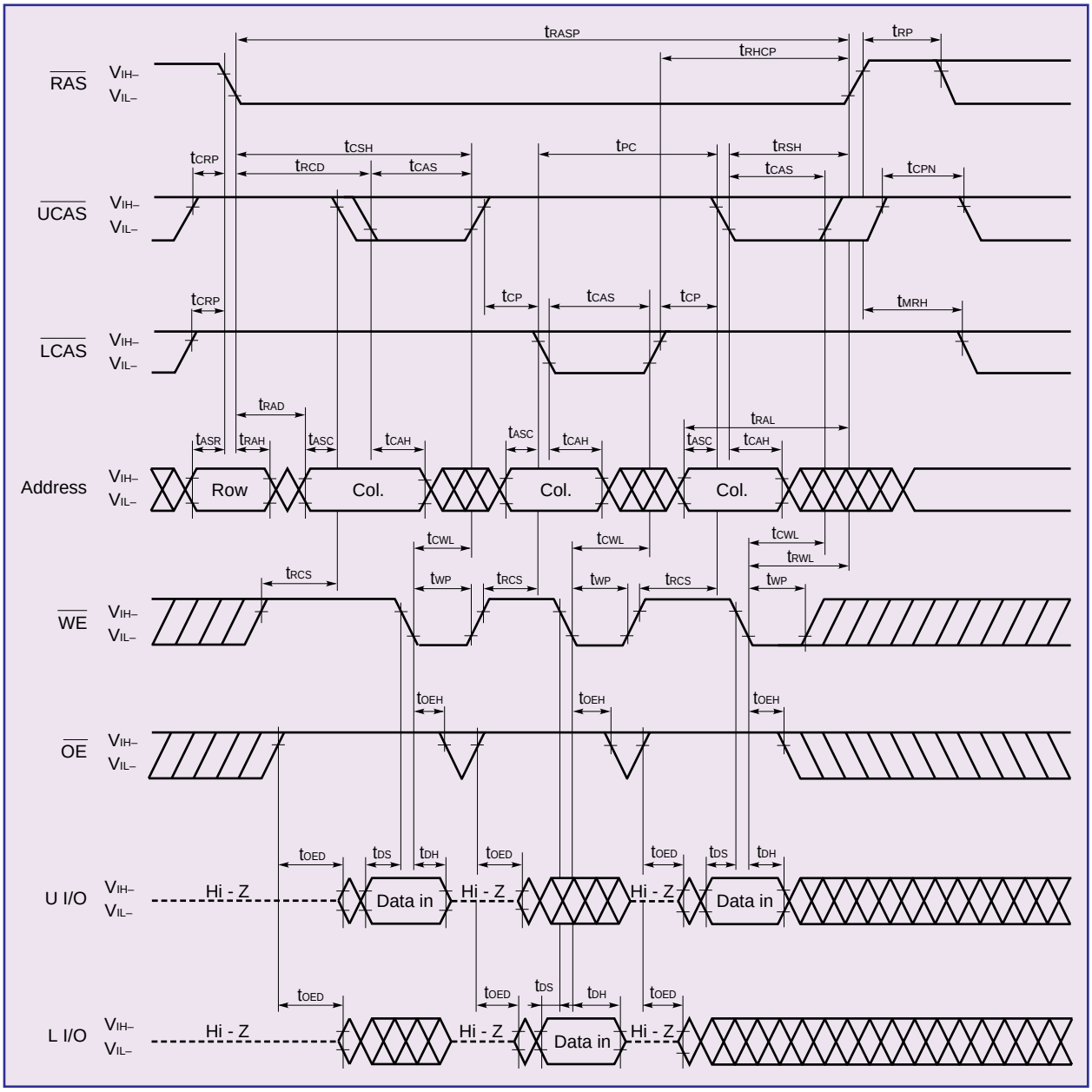
2. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.
3. This cycle can be used to control either $\overline{UCAS}$ or $\overline{LCAS}$ only. Or, it can be used to control $\overline{UCAS}$ or $\overline{LCAS}$ simultaneously, or at random.

Fast Page Mode Late Write Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

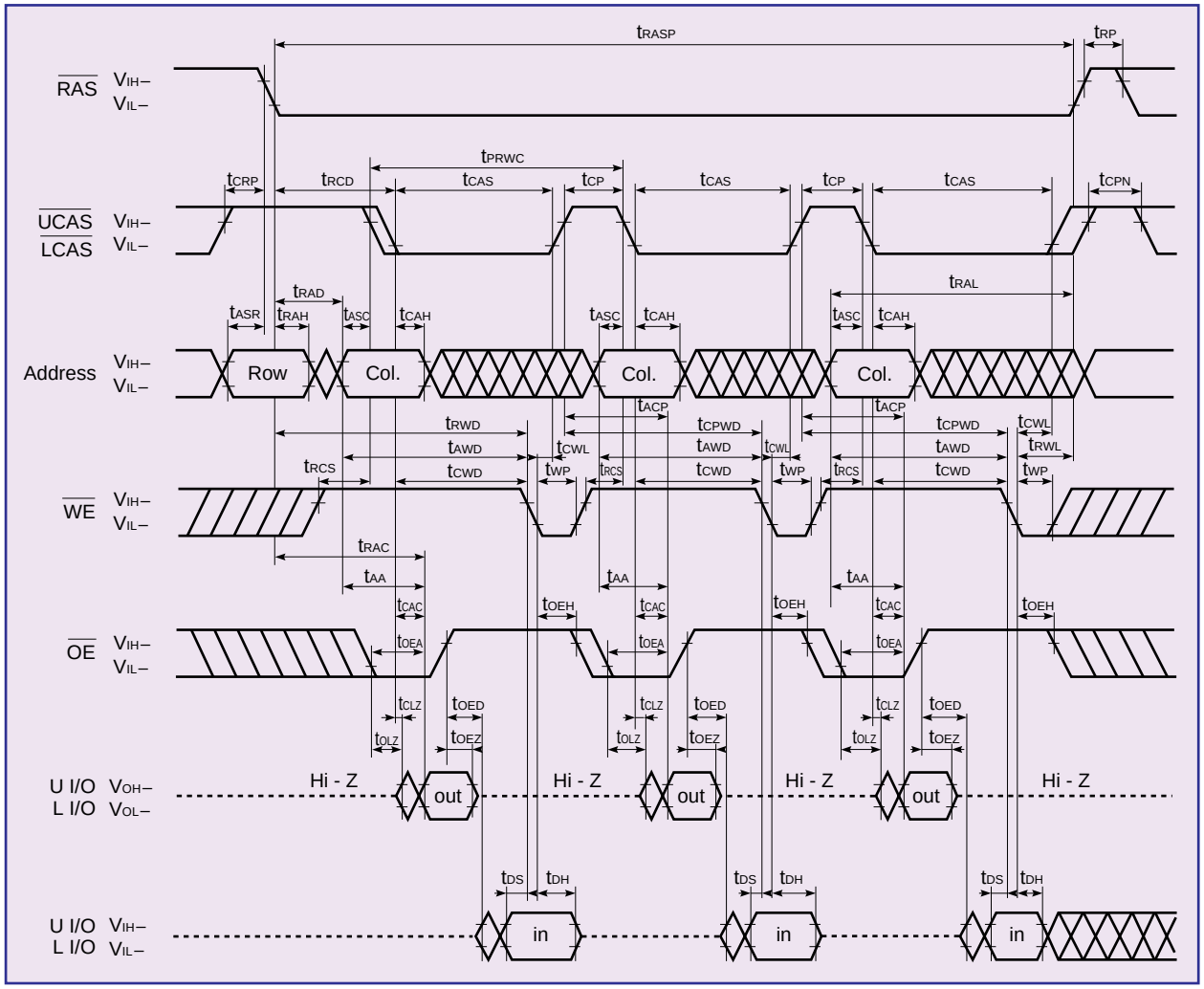
Fast Page Mode Byte Late Write Cycle



Remarks 1. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

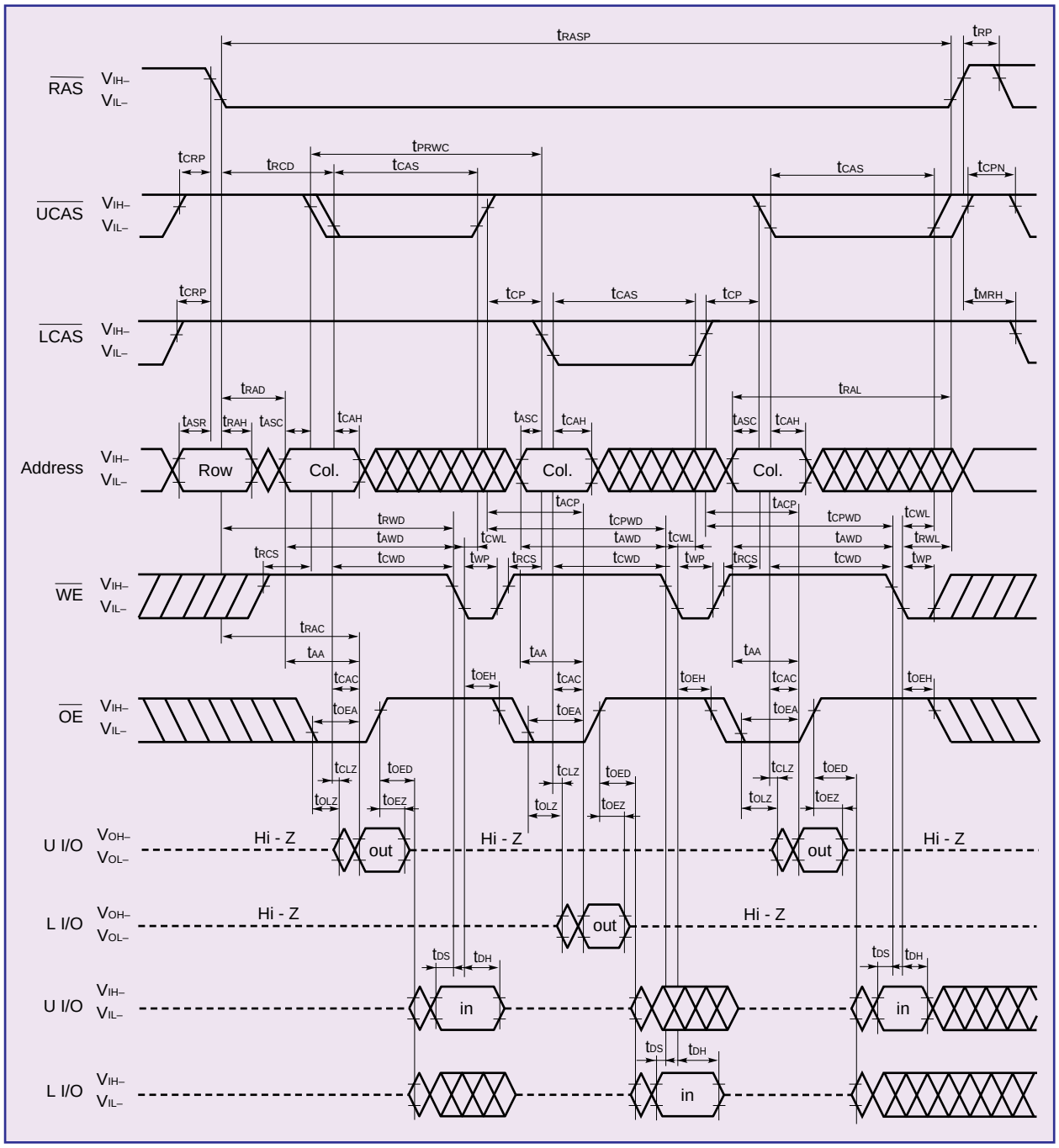
2. This cycle can be used to control either $\overline{UCAS}$ or $\overline{LCAS}$ only. Or, it can be used to control $\overline{UCAS}$ or $\overline{LCAS}$ simultaneously, or at random.

Fast Page Mode Read Modify Write Cycle



Remark In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

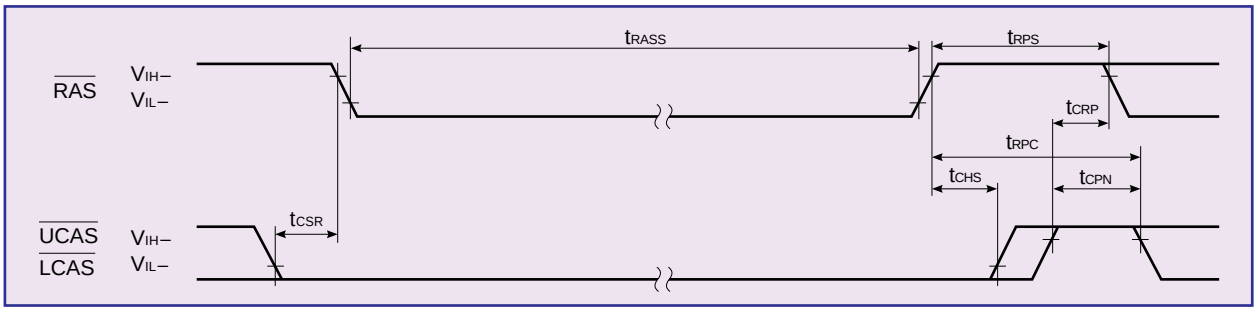
Fast Page Mode Byte Read Modify Write Cycle



Remarks 1. In the fast page mode, read, write and read modify write cycles are available for each of the consecutive $\overline{CAS}$ cycles within the same $\overline{RAS}$ cycle.

2. This cycle can be used to control either $\overline{UCAS}$ or $\overline{LCAS}$ only. Or, it can be used to control $\overline{UCAS}$ or $\overline{LCAS}$ simultaneously, or at random.

CAS Before RAS Self Refresh Cycle (Only for the *m*PD42S4260)



Remark Address, WE, OE: Don't care L I/O, U I/O: Hi-Z

Cautions on Use of CAS Before RAS Self Refresh

CAS before RAS self refresh can be used independently when used in combination with distributed CAS before RAS long refresh; However, when used in combination with burst CAS before RAS long refresh or with long RAS only refresh (both distributed and burst), the following cautions must be observed.

(1) Normal Combined Use of CAS Before RAS Self Refresh and Burst CAS Before RAS Long Refresh

When CAS before RAS self refresh and burst CAS before RAS long refresh are used in combination, please perform CAS before RAS refresh 512 times within an 8 ms interval just before and after setting CAS before RAS self refresh.

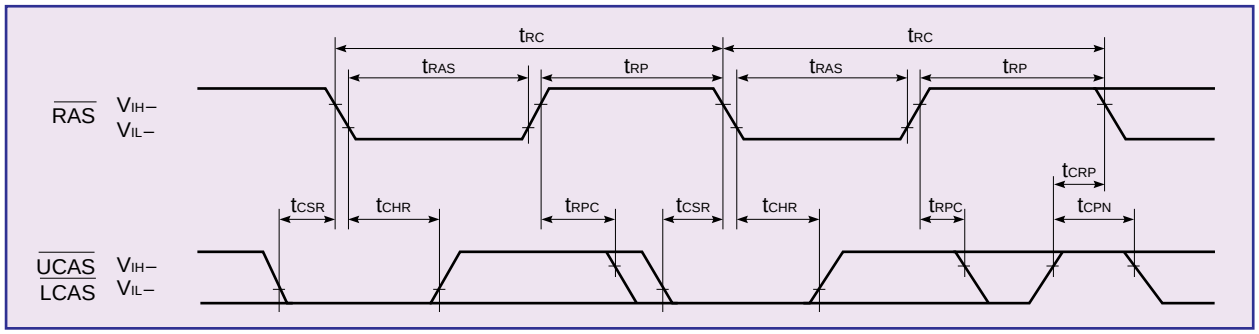
(2) Normal Combined Use of CAS Before RAS Self Refresh and Long RAS Only Refresh

When CAS before RAS self refresh and RAS only refresh are used in combination, please perform RAS only refresh 512 times within an 8 ms interval just before and after setting CAS before RAS self refresh.

★ **(3)** If $t_{RASS\ (MIN.)}$ is not satisfied at the beginning of CAS before RAS self refresh cycles (t_{RAS} < 100 μs), CAS before RAS refresh cycles will be executed one time.
If 10 μs < t_{RAS} < 100 μs, RAS precharge time for CAS before RAS self refresh (t_{RPS}) is applied.
And refresh cycles (512/128 ms) should be met.

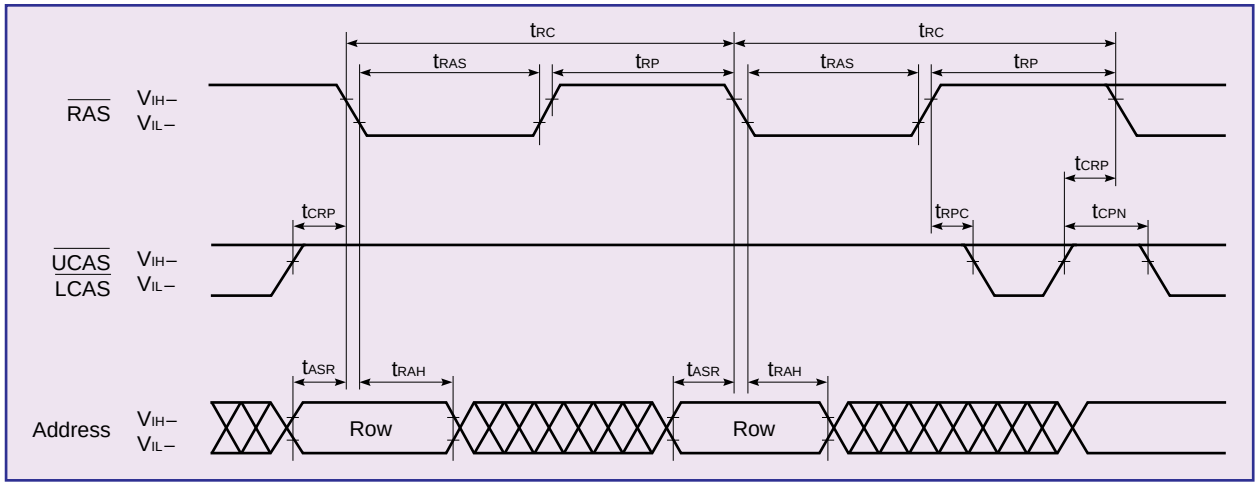
For details, please refer to **How to use DRAM** User's Manual.

$\overline{\text{CAS}}$ Before $\overline{\text{RAS}}$ Refresh Cycle



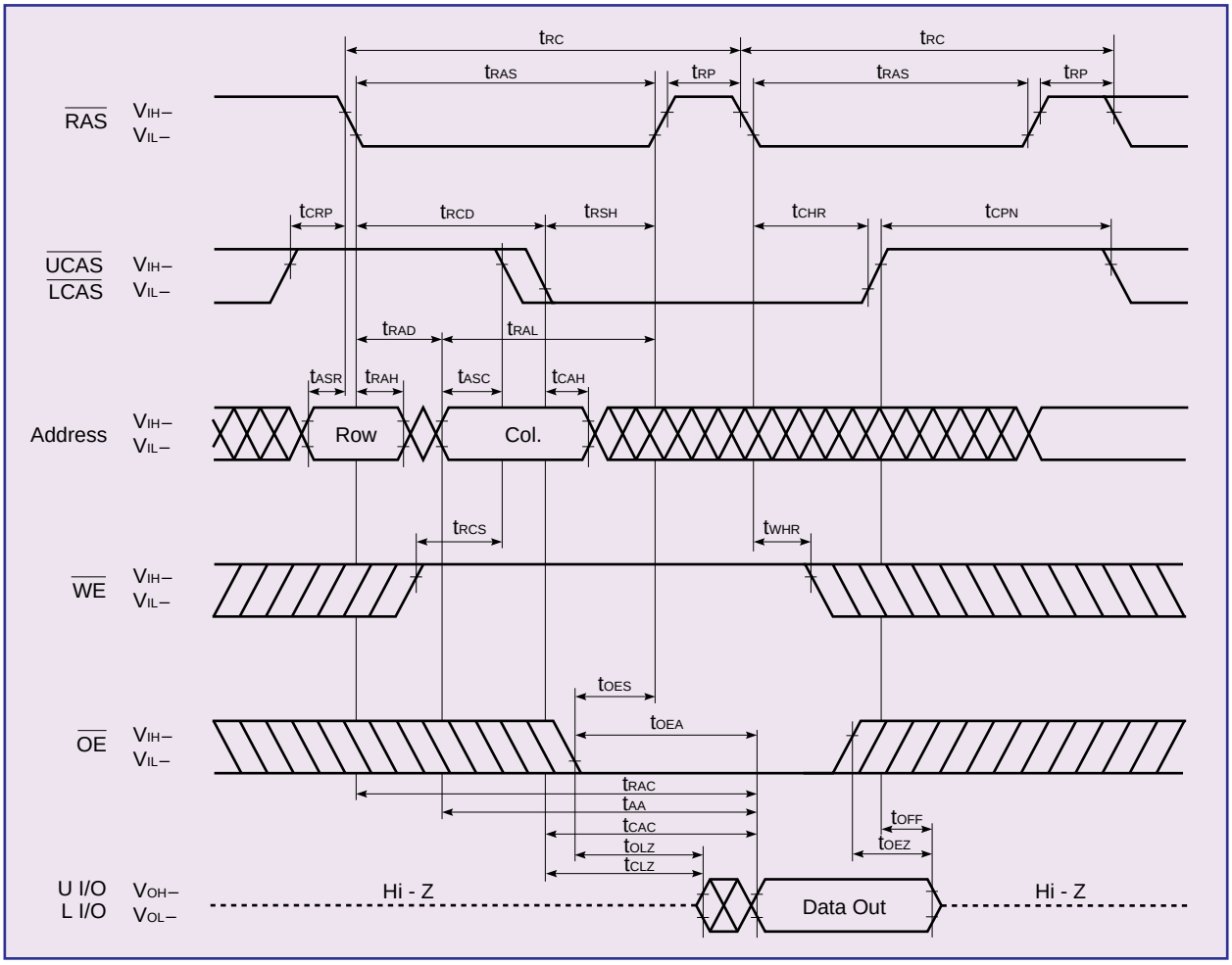
Remark Address, $\overline{\text{WE}}$, $\overline{\text{OE}}$: Don't care L I/O, U I/O: Hi-Z

$\overline{\text{RAS}}$ Only Refresh Cycle

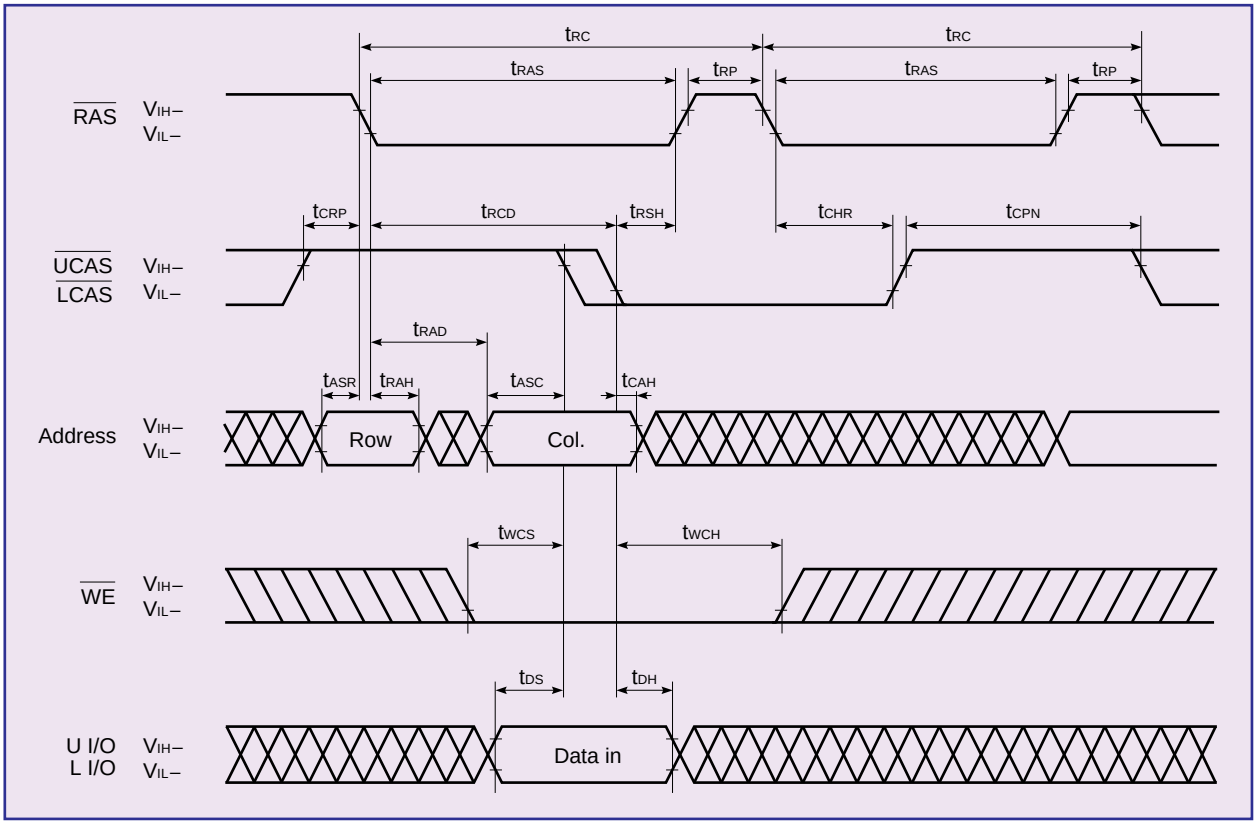


Remark $\overline{\text{WE}}$, $\overline{\text{OE}}$: Don't care L I/O, U I/O: Hi-Z

Hidden Refresh Cycle (Read)



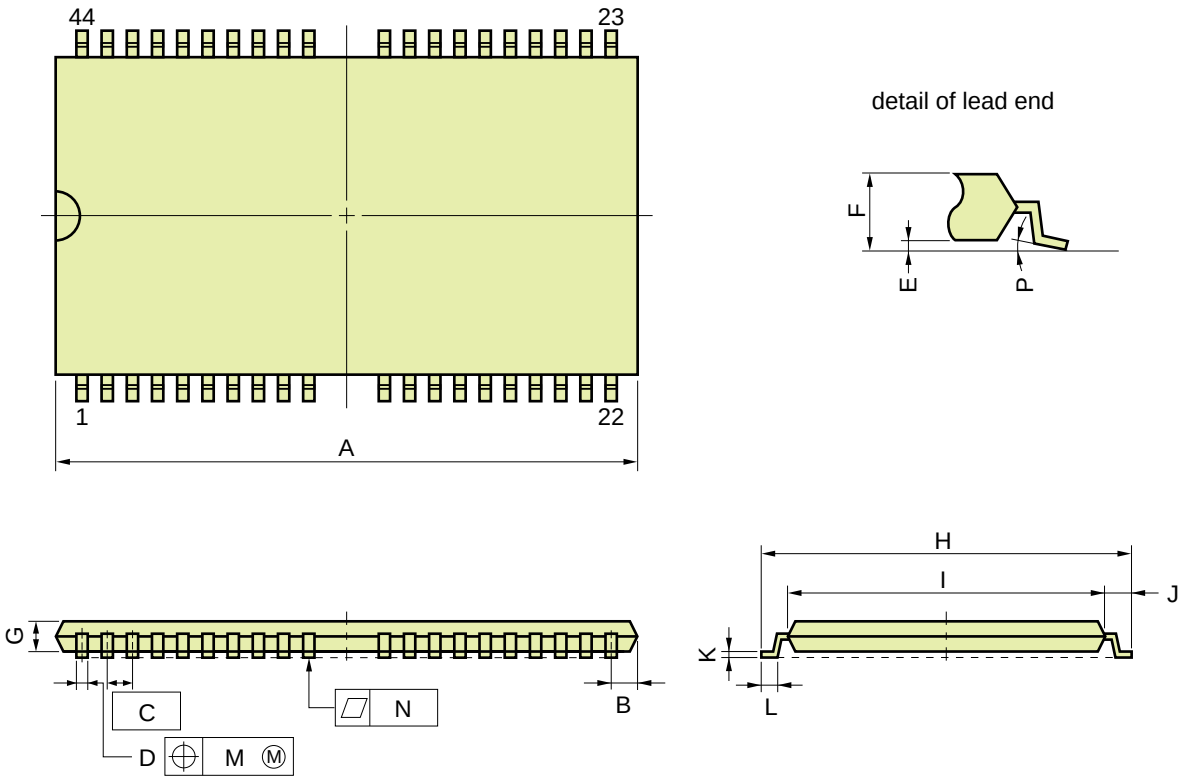
Hidden Refresh Cycle (Write)



Remark $\overline{OE}$: Don't care

Package Drawings

44 PIN PLASTIC TSOP(II) (400 mil)



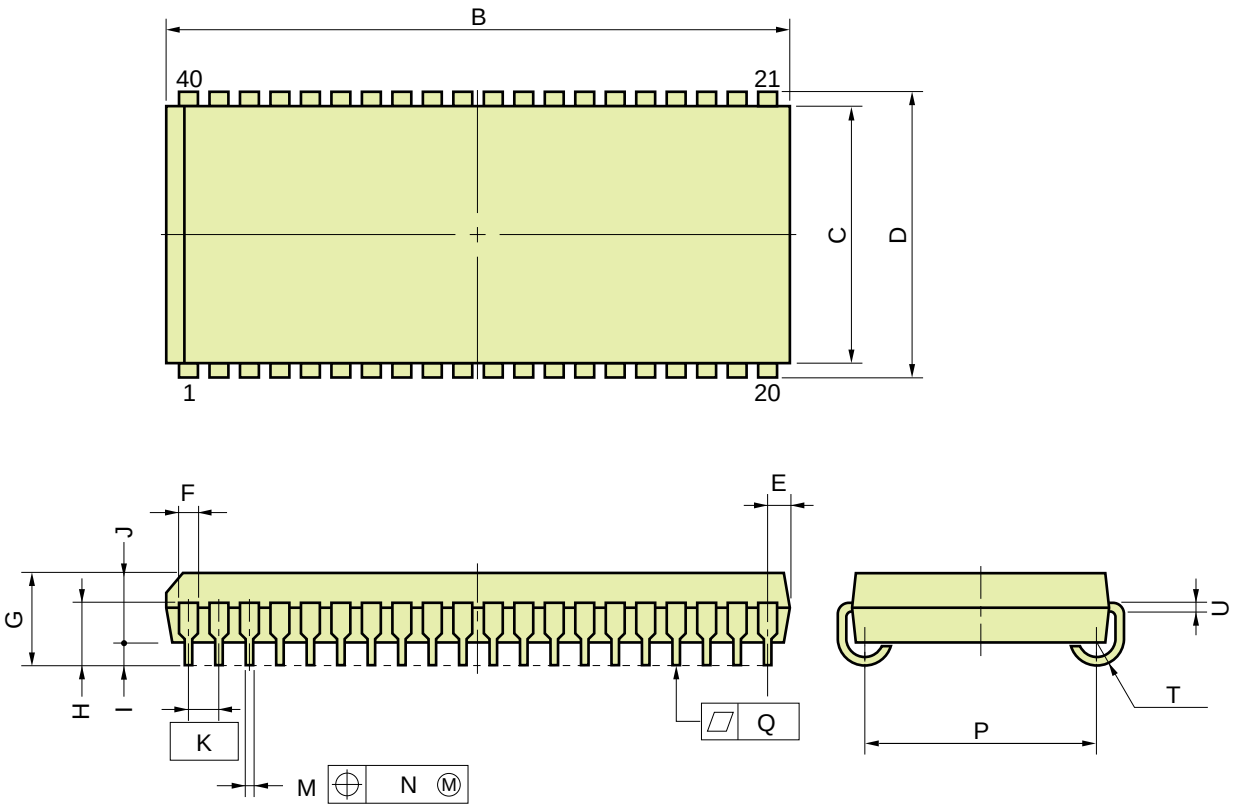
NOTE

Each lead centerline is located within 0.13 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
A	18.63 MAX.	0.734 MAX.
B	0.93 MAX.	0.037 MAX.
C	0.8 (T.P.)	0.031 (T.P.)
D	$0.32^{+0.08}_{-0.07}$	0.013±0.003
E	0.1±0.05	0.004±0.002
F	1.2 MAX.	0.048 MAX.
G	0.97	0.038
H	11.76±0.2	0.463±0.008
I	10.16±0.1	0.400±0.004
J	0.8±0.2	$0.031^{+0.009}_{-0.008}$
K	$0.145^{+0.025}_{-0.015}$	0.006±0.001
L	0.5±0.1	$0.020^{+0.004}_{-0.005}$
M	0.13	0.005
N	0.10	0.004
P	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$	$3^{\circ}{}^{+7^{\circ}}_{-3^{\circ}}$

S44G5-80-7JF4

40 PIN PLASTIC SOJ (400 mil)



NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS	INCHES
B	$26.29^{+0.2}_{-0.35}$	$1.035^{+0.008}_{-0.014}$
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.08±0.15	$0.043^{+0.006}_{-0.007}$
F	0.7	0.028
G	3.5±0.2	0.138±0.008
H	2.4±0.2	$0.094^{+0.009}_{-0.008}$
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27(T.P.)	0.050(T.P.)
M	0.40±0.10	$0.016^{+0.004}_{-0.005}$
N	0.12	0.005
P	9.40±0.20	0.370±0.008
Q	0.15	0.006
T	R0.85	R0.033
U	$0.20^{+0.10}_{-0.05}$	$0.008^{+0.004}_{-0.002}$

P40LE-400A-2

Recommended Soldering Conditions

The following conditions (see tables below and next page) must be met when soldering μPD42S4260, 424260.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (IEI-1207).

Please consult with our sales offices in case other soldering process is used, or in case the soldering is done under different conditions.

Types of Surface Mount Device

μPD42S4260G5-7JF, 424260G5-7JF: 44-pin plastic TSOP (II) (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface: 235 ˚C or lower, Reflow time: 30 seconds or less (210 ˚C or higher), Number of reflow processes: MAX. 2 Exposure limit: 7 days[Note] (10 hours pre-baking is required at 125 ˚C afterwards) **Cautions** **1. After the first reflow process, cool the package down to room temperature, then start the second reflow process.** **2. After the first reflow process, do not use water to remove residual flux (water can be used in the second process).**	IR35-107-2
VPS	Peak temperature of package: 215 ˚C or lower, Reflow time: 40 seconds or less (200 ˚C or higher), Number of reflow processes: MAX. 2 Exposure limit: 7 days[Note] (10 hours pre-baking is required at 125 ˚C afterwards) **Cautions** **1. After the first reflow process, cool the package down to room temperature, then start the second reflow process.** **2. After the first reflow process, do not use water to remove residual flux (water can be used in the second process).**	VP15-107-2
Partial heating method	Terminal temperature: 300 ˚C or lower, Time: 3 seconds or less (Per side of the package).	—

Note Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 ˚C and relative humidity at 65 % or less.

Caution **Do not apply more than one soldering method at any one time, except for "Partial heating method".**

μPD42S4260LE, 424260LE: 40-pin plastic SOJ (400 mil)

Soldering process	Soldering conditions	Symbol
Infrared ray reflow	Peak temperature of package surface: 235 ˚C or lower, Reflow time: 30 seconds or less (210 ˚C or higher), Number of reflow processes: MAX. 2 Exposure limit: 7 days[Note] (20 hours pre-baking is required at 125 ˚C afterwards) **Cautions** **1. After the first reflow process, cool the package down to room temperature, then start the second reflow process.** **2. After the first reflow process, do not use water to remove residual flux (water can be used in the second process).**	IR35-207-2
VPS	Peak temperature of package: 215 ˚C or lower, Reflow time: 40 seconds or less (200 ˚C or higher), Number of reflow processes: MAX. 2 Exposure limit: 7 days[Note] (20 hours pre-baking is required at 125 ˚C afterwards) **Cautions** **1. After the first reflow process, cool the package down to room temperature, then start the second reflow process.** **2. After the first reflow process, do not use water to remove residual flux (water can be used in the second process).**	VP15-207-2
Partial heating method	Terminal temperature: 300 ˚C or lower, Time: 3 seconds or less (Per side of the package).	—

Note Exposure limit before soldering after dry-pack package is opened.
Storage conditions: 25 ˚C and relative humidity at 65 % or less.

Caution **Do not apply more than one soldering method at any one time, except for "Partial heating method".**